

Minutes of Meeting

Herschel

Date: 21.01.2003

Doc.-No.: HP-2-ASED-MN-0265

Meeting place: Ottobrunn

Chairman: *S. Idler*

Date/Time: 21.01.2003 / 9:00

Secretary: *C. Schlusser*

Agenda dated: 18.12.2002

Close of Meeting:

Subject: Instrument AIT Meeting

Participants:
see list on next page

Additional Distribution:

Page: 1 of Page(s)

Brief-Minutes (except following sheets)

Summary of Results of Sheets 2 till

Common instrument AIT aspects have been discussed and some open points were identified. Next common instrument AIT meeting is in CW 21/03.

Reference	Results	Remarks
	<p><u>Agenda</u> see ASED presentation in annex 1</p> <p><u>Introduction</u> Satellite level instrument AIT approach is given and will be updated in test plan, HP-2-ASED-PL-0021 (EQM) and HP-2-ASED-PL-0031 (PFI)</p> <p>These are top-level documents, forming the baseline for Instrument AIT procedures.</p> <p><u>Integration</u> WU test after integration: PACS: no FPM simulator necessary, test data will from BOLC and DECASC. PLM EGJE is the same on EQM as on PFI. First tests on PFI will be done on PLI level</p>	

Reference	Results	Remarks
	<p>using the PLT EGJE.</p> <p>First EMC test on PFM (CE, CJ) will be done on PLT level.</p> <p>AJED to send the EQP and PFM AIT flow to instruments.</p> <p>A HIFI LOU simulator would be preferred. HIFI internal discussion is ongoing.</p> <p>An FPU simulator is not necessary if the WU have the capability to work without the FPU, simulating "normal" data traffic (only for AVI tests)</p> <p><u>FPU integration</u></p> <p>PACJ requires to use the HYDRAJET for mech. integration (tbd)</p> <p>No mechanical machining is allowed in CR 100.</p> <p>There should not be a special sequence for FPU integration necessary. This has to be checked w.r.t. SPIRE footprint</p>	<p>AI #1 ASED 31.1.03</p>

Reference	Results	Remarks
	<p>PACS presentation demonstrates FPU integration on board of the FPU STM integration on instrument level. (See annex 2)</p> <p>HIFI presentation demonstrates FPU integration using drawings. (See annex 3)</p> <p>PACS do provide first draft of FPU integration procedure.</p> <p>^{HIFI} FPU integration approach seems to be valuable. Details will be discussed tomorrow.</p> <p><u>Built standard</u></p> <p>HIFI EQM built standard has been presented.</p> <p>Potential I/F to HIFI heaters will be discussed tomorrow. Supply by Cryo SCOS has to be discussed.</p> <p>Envelope of WU is the same ^{on EQM} as on FP.</p>	<p>AS #2 PACS #3 deleted</p>

Reference	Results	Remarks
	<p>PACS EQM built standard has been presented. Not all PACS units are representative in form (only fit and function). PACS to deliver drawings of these units</p> <p>(The cryo harness is near identical on PFT and EQM. Therefore derivation of not used I/F has to be provided at the instrument units. The only difference could be the length of the harness.</p> <p><u>EGJE / Testing</u></p> <p>ESTEC presentation (annex 4) of ISTJ approach</p> <p>3 ways of instrument EGJE considered:</p> <ul style="list-style-type: none"> • 1-EGJE off • 1-EGJE in listening mode (from CCS) • 1-EGJE interactive via CCS <p>1-EGJE will be in listening mode and real time mode during I/F, depending on test phase / test objective.</p>	<p>AI #4 PACS</p>

Reference	Results	Remarks
	<p>Next steps: Herschel IST specifications to be prepared by ASP1</p> <p>Overall EGIE presentation by Alcatel (annex 5):</p> <p>WiFi needs a stimuli during EMC testing. This should be under remote control from CCS. WiFi to define details</p> <p>New I/F between I-EGIE and CCS (RC, ACK RC) to be defined as on I/F to the SCES.</p> <p>Instrument EGIE presentation by OBO Bauer (annex 6)</p> <p>Total test duration during IST ~ 4 d/instrument.</p> <p>2 complete I-EGIE systems will be provided (1 real time, 1 for analysis) for all instruments together. ^{for each model} Overall EGIE concept has to be updated by ASP1.</p> <p>Requested industry support will be</p>	<p>AI#5 WiFi</p>
	<p>discussed during EGIE working group meeting on 5.2.03.</p>	

Reference	Results	Remarks
	<p>CCS / I-EGSE VF check shall be done <u>in advance</u>.</p> <p>Presentation of I-EGSE on PLN and Satellite level by ESA (annex 7)</p> <p>Problems:</p> <ul style="list-style-type: none"> - If a test stops for any reason, it has to be repeated completely <p>EQM:</p> <ul style="list-style-type: none"> - IMT (Integrated Module Test) is a functional performance test of the instruments <p>Concept: Test sequence is running on CCS. Observation information is in the HCSS.</p> <p>Handshake between CCS and HCSS during IST is not totally clear to all parties. This will be part of the <u>EGSE working group meeting</u></p> <p>PACS propose to modify the LAN + AVN ILT program presented (annex 8)</p>	

Reference	Results	Remarks
	<p>Cryogenic qualification with and no cold vibration with cam. TPU HTT. Due to parallel activities gap of 33 day feasible. To be discussed with ESA during next HT meeting (?).</p> <p><u>Test Constraints</u></p> <p>Tilting analysis performed for FT (see HP-2-ASED-TN-0068)</p> <p>No problems have been detected for PACJ.</p> <p>SPIRE spectrometer mode inside LJJ is not possible with the present configuration It is under investigation to perform this test outside the chamber.</p> <p>Due to position of the Lθ interfaces, WIFI tests inside the LJJ would only be possible in the very beginning of the TVITB test. Therefore, extension of the Lθ inside the HTT is under investigation. Test derivations for instrument tests during TVITB test are needed to support this investigation.</p>	<p>AI # 6 WIFI (PACJ, HTRE)</p>

Reference	Results	Remarks
	<p>PACS will make a suggestion how to verify this I/F.</p> <hr/> <p>EMC test approach TBCs in E&M EMC are coming from a CR/ED, which is currently in the pipeline. RIFI states that there is a risk, that no SIC level EMC test can be performed on E&M. CE/CS will be performed on PFM SIC level. (not covered in handout)</p> <hr/> <p>TBITV Test approach Major concerns w.r.t. instrument testing are the liquid content ($\approx \pm 25^\circ$) and the tilting constraints inside the chamber. At the moment no sun simulation is foreseen.</p> <hr/> <p>Future Instrument BIT meeting approach:</p>	

Reference	Results	Remarks
	<p>Even if it is difficult to arrange a meeting with all instruments, it shall be maintained to have this level of meeting on a regular basis. Instrument specific AIT aspects can as well be discussed in the instrument V/E meeting.</p> <p>Next instrument AIT meeting shall take place in CW 21/03. (21.05.2003 - tbc.)</p>	

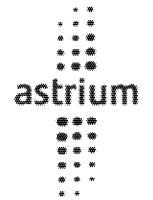
Meeting: HP-2-ASED-MN-0265
 Title: Instrument AIT Meeting
 Date: 21.01.2003

Action Item List

Herschel

No.:	Description:	Due Date	Originator Comp./Pers.	Actionee Comp./Pers.	Source	Completion
1	Update EQM/PFA AIT flow to be distributed	28.2.03	ALC, Houlet	Th. Rayer		
2	PACJ to provide 1 st draft of integration proced	28.2.03	D. Schiick	O. Bauer		
3	deleted	—				
4	PACJ to provide drawings of AVIT units	28.02.03	D. Schiick	O. Bauer		
5	HIFI to define instrument stimuli for ETC test	28.02.03	S. Lollar	K. Wafelbacher		
6	Instrument to define test durations during TBTV	28.02.03	S. Lollar	K. Wafelbacher		
7	HIFI to define purging requirements in detail	31.01.03	D. Schiick S. Lollar	O. Bauer K. Wafelbacher		
8	HIFI to specify differences between EQM and FIT testing	28.2.03	S. Lollar	K. Wafelbacher		
	PACJ	28.2.03	D. Schiick	O. Bauer		
	SPIRE	28.2.03				

✓ P1



Reference	<u>Participants</u>	<u>Results</u>	Remarks
	C. Schlower	ASED (L)	
	R. Katterloher	MPE (Kleber)	
	O. H. Pauer	MPE	
	N. D. Whyborn	SRON	
	Th. Jager	ASED	
	M. Kalle	ASED	
	B. Melton	ESTEC	
	W. Luinger	SRON (Wey)	
	M. von Berg	MPE	
	J. Schubert	MPE	
	K. J. Wildeman	SRON	
	G. Lund	ALCATEL	
	S. IDLER	ASED	
	W. Ruhe	ASED	
		D. Schink	ASED
		N. Niedetzky	ESTEC
		A. Naber	SRON
		K. Wafelbakker	SRON
		O. PIERJANTI	ESTEC (M)
		G. DOUBROVIK	ALCATEL
		D. MONTET	ALCATEL

**Herschel
Instruments AIT Meeting**



Siegmund Idler
21.01.2003

AMVEX 1

Instruments AIT Meeting - Introduction

Agenda (as per HP-ASED-FX-0836-02 & e-mail from Denis Montet) (1)

- Introduction
- Integration
 - Integration sequence
 - FPU's integration constraints
 - MGSE interfaces
- Test configuration
 - Presentation of Alcatel with respect to interfaces between CCS and instrument EGSE
 - Presentation of Otto Bauer with respect to activities of the EGSE working group,
 - Build standard of deliverable items
- Test constraints
 - Tilting
 - Purging
 - Standing wave test limitations
 - CQM/AVM test limitations

Instruments AIT Meeting - Introduction

Agenda (as per HP-ASED-FX-0836-02 & e-mail from Denis Montet) (2)

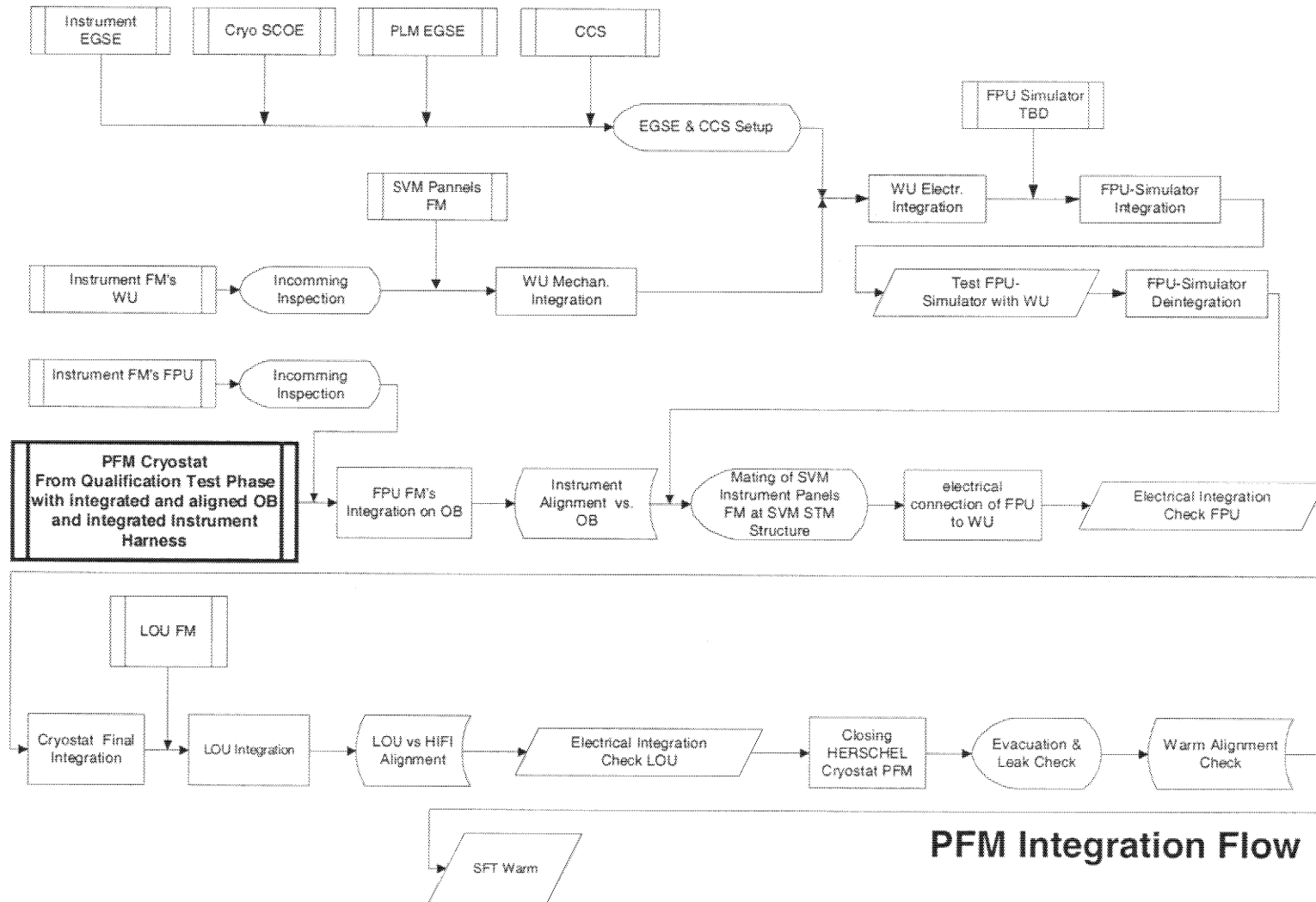
- EQM/FM testing
 - Electrical integration check
 - EMC/ESD
 - TB/TV
 - Presentation of ESTEC with respect to IST approach
- AOB
- Agreement on future meetings
- Close-out of minutes

Instruments AIT Meeting - Introduction

Scope and objectives of HP-2-ASED-PL-0021/0031

- Container for all information related to satellite level instrument AIT activities
- Tool for co-ordination of satellite level instrument AIT activities
- Basis for establishment of test procedures
- All instrument related aspects in one document
- Tailoring to instrument related aspects
- Regular updates
- Instrument suppliers are asked to regularly comment the documents and to provide all new AIT relevant data to be included therein

Instruments AIT Meeting - Integration



PFM Integration Flow

Instruments AIT Meeting - Integration

FPU's integration constraints

- PLM integrated on rotary table
- PLM with x-axis in vertical position
- Facility constraints:
 - Crane velocity 1-5 m/min
 - Lowering speed 0.2-4 m/min (3 mm/sec)
 - For further reduction of lowering rate a HYDRASET is available

Instruments AIT Meeting - Integration

FPU's integration requirements

- No mechanical machining or adaptation of OBA after integration (clean room class 100)
- Access to all MGSE interfaces with integration tools at fully integrated OBA mandatory
- Access to all thermal, mechanical and electrical FPU interfaces at fully integrated OBA mandatory
 - Access to all thermal links
 - Access to all mounting feet
 - Access to all connectors for mating/de-mating
 - Red tag items (protections needed for integration) must be removable
- The use of instrument hoisting devices (MGSE) shall not impose a sequence for the FPU integration
- Special integration tools, if needed, to be provided by instruments

Instruments AIT Meeting - Integration

Items to be clarified

- FPU thermal interfaces (accessibility at fully integrated OBA)
- FPU integration procedure from PACS and SPIRE
- HIFI FPU MGSE/hoisting device
- HIFI LOU integration/alignment procedure and MGSE/hoisting device

Instruments AIT Meeting - Test Configuration

EGSE interfaces

- See presentation of Alcatel and Otto Bauer

Instruments AIT Meeting - Test Configuration

Build standard of deliverable items

- The following information is available at ASED:
 - HIFI: HP-HIFI-CR-0066, dated 30.09.2002, update requested by HP-ASPI-MN-2241, AI 05
 - PACS: HP-2-ASED-PL-0021, § 5.1.2, to be updated as per e-mail from Reinhard Katterloher to Dietmar Schink, dated 17/01/03
 - SPIRE: HP-2-ASED-PL-0021, § 5.1.3, will be updated by SPIRE (see annex to e-mail from Bruce Swinyard to Siegmund Idler, dated 11/12/02)
- The following information is required:
 - Detailed information of built standard of FPU CQM's and AVM's
 - Identification in what they differ from PFM's in form, fit and function
 - Electrical interface description (differences with respect to PFM, if any)

Instruments AIT Meeting - Test Constraints

Herschel Tilting Analysis (HP-2-ASED-TN-0068, issue 1)

Scope of analysis

- Analysis of impact of all relevant tilting requirements and constraints on the Herschel PFM during the ground test activities:
 - at H-EPLM level and
 - at spacecraft level
- Recommendations how to perform tilting operations efficiently during the testing to fulfil the thermal interface requirements
- A tilting analysis for the PLM EQM ground testing will be included in a later issue

Instruments AIT Meeting - Test Constraints

Herschel Tilting Analysis (HP-2-ASED-TN-0068, issue 1) Requirements and constraints

- Instrument tilting requirements for PACS and SPIRE during
 - Cooler recycling (duration 2h)
 - A subset of instrument tests (test duration 2h)
- Tilting constraints from cryostat geometry for the following components:
 - Passive Phase Separator (PPS)
 - Gaseous He outlet
 - Rupture Disc (RD124)
 - He II Tank (HTT) internal Level-0 strap extensions
 - Filling Port
 - Cryo cover cooling GSE
- Tilting constraints in integration and test facilities and during transport

Instruments AIT Meeting - Test Constraints

Herschel Tilting Analysis (HP-2-ASED-TN-0068, issue 1)

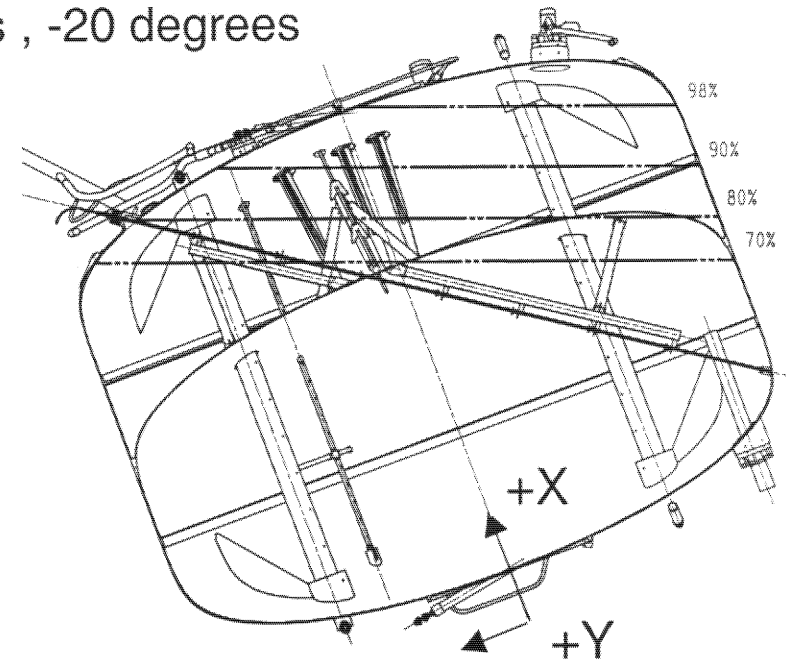
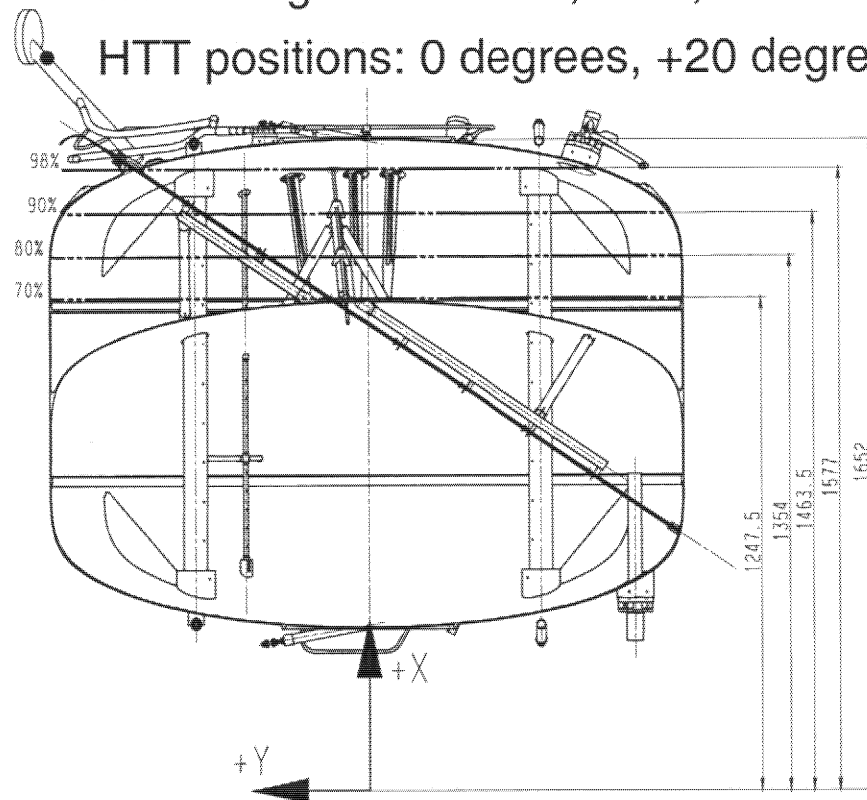
Analysed test set-ups and StM/PFM tests

- He-Subsystem test set-up during ground tests
 - Test set-up in ambient environment
 - TB/TV test set-up
- Instrument Short Functional and Specific Performance Tests (SFT, SPT)
- Integrated Module Tests (IMT)
- Integrated System Tests (IST)
- TB/TV tests
- System Validation Tests (SVT)

Instruments AIT Meeting - Test Constraints

Herschel Tilting Analysis (HP-2-ASED-TN-0068, issue 1) Analysed He II Tank (HTT) filling levels and positions

- HTT filling levels: 98%, 90%, 80% and 70%
- HTT positions: 0 degrees, +20 degrees, -20 degrees



Instruments AIT Meeting - Test Constraints

Herschel Tilting Analysis (HP-2-ASED-TN-0068, issue 1)

Conclusions as regards instrument tests

- Tilting requirements for PACS and SPIRE cooler recycling in the same direction as needed to bring the He to the respective level-0 interfaces.
- All PACS and SPIRE tests including PACS/SPIRE parallel mode testing can be performed.
- Inside the LSS, PACS and SPIRE tests can be performed down to a He II filling level of about 84%, respectively 79%.
- SPIRE spectrometer test inside the LSS is with the existing LSS motion systems not feasible. Analysis to be performed whether orbit representative and stable conditions could be achieved outside the TV/TB test.
- The ability to perform the HIFI tests is only given during the very beginning of the TB/TV test. The foreseen level-0 interface extensions shall ensure that the HIFI tests can be performed without limitations.
- Transport of PLM and satellite to be performed in horizontal position and with reduced liquid He level < 50%.

Instruments AIT Meeting - Test Constraints

Purging

- HIFI require purging of FPU and LOU (HIFI-CR-0062 and -0064)
- No purging requirements for PACS and SPIRE
- Required inputs from HIFI (see also HP-ASPI-MN-2241):
 - Clarification of / agreement on inlet/outlet interfaces
 - Max. allowed time without purging
 - Required flow rate and purity of purge gas
 - Driving requirements for purging (e. g. cleanliness, moisture)

Instruments AIT Meeting - Test Constraints

Standing wave test limitations (HIFI)

- Test of standing waves between LOU and FPU by measuring of LO to mixer coupling as function of LO frequency
 - No requirement on cryo cover concerning background simulation
 - Thermal/mechanical test constraints to be specified (e. g. temperature stability)
- Test of standing waves within or near the beam path from telescope to FPU not planned
 - Representative test would need telescope, i. e. must be performed on spacecraft level with open cover in LSS
 - Dedicated mechanism needed to close cover
 - Risk: cover closure failure

Instruments AIT Meeting - Test Constraints

CQM/AVM test limitations

- Differences between CQM/AVM and PFM models with regard to test constraints and test sequences to be clarified.

Instruments AIT Meeting - EQM/PFM Testing

Electrical integration check (FPU to Warm Units interface) (1)

- Electrical interface checks shall be performed before connecting the harness to the corresponding unit or instrument
- S/C AIT approach:
 - Flight harness continuity check (Warm Units and FPU's not connected)
 - Warm Units grounding, shielding and isolation verification via cryo harness (Warm Units connected and off, FPU's not connected)
 - Warm Units output signals verification via cryo harness (Warm Units connected and powered, FPU's not connected)
 - Measurement versus FPU's currently not planned (safety reasons)
 - Warm Units output signals verification via cryo harness using T-adapter (Warm Units and FPU's connected and powered)

Instruments AIT Meeting - EQM/PFM Testing

Electrical integration check (FPU to warm units interface) (2)

- Measurement performed using Integration Data Acquisition System (IDAS)
 - Computer supported measurement equipment
 - Automatic testing and test evaluation
 - Measurement capability for resistance, voltage, currents, pulses, timing and frequencies
 - Successful used for e. g. XMM and METOP
- Verification based on EICD (HP-2-ASED-IC-0001)
 - Derived from IID-B's
 - Also used for harness manufacturing
- Points to be clarified
 - EICD data base verification (e. g. by comparison with data base used for test harness manufacturing/verification)
 - Signals to be checked

Instruments AIT Meeting - EQM/PFM Testing

EMC test approach (1)

Configuration:	
EQM Integrated Module	<ul style="list-style-type: none"> • ISO modified QM Cryostat • Optical Bench Assembly • CQM FPU's/Outer CVV electronic (LOU) and CVV instrumentation • CVV inner cryo harness, el. representative • CVV outer cryo-harness, representative • CVV cover closed • Avionics Modules: Warm units integrated in a SVM dummy and interconnected with representative harness. • No telescope, no sunshield/sunshade
PFM Integrated Module	<ul style="list-style-type: none"> • Full flight configuration except: <ul style="list-style-type: none"> - CVV cover closed - No Telescope - No sunshield/sunshade
PFM Herschel S/C	<ul style="list-style-type: none"> • Full flight configuration except: <ul style="list-style-type: none"> - CVV cover closed

Instruments AIT Meeting - EQM/PFM Testing

EMC test approach (2)

	Facility
EQM Integrated Module	<ul style="list-style-type: none">• Cleanroom 100000
PFM Integrated Module	<ul style="list-style-type: none">• Cleanroom 100000
PFM Herschel S/C	<ul style="list-style-type: none">• Cleanroom 100000 / anechoic chamber (for RE)

Instruments AIT Meeting - EQM/PFM Testing

EMC test approach (3)

EMC Tests	
EQM Integrated Module	<ul style="list-style-type: none">• CE/CS on warm units• CS on cryoharness bundles (tbc) (see below)• CS on cryoharness simulating RS (tbc) (see below)• ESD• RS (tbc) (see below)
PFM Integrated Module	<ul style="list-style-type: none">• CE/CS on warm units• No RE/RS
PFM Herschel S/C	<ul style="list-style-type: none">• No CE/CS• RE/RS (to cover compatibility to launcher)

Instruments AIT Meeting - EQM/PFM Testing

EMC test approach (4)

Test Descriptions

1. CS Common Mode Current on Cryo Harness Bundles ([RD1], §. 6.3.1.1)

Test method: Sine wave injection CM plus CE - CM current emissions (to define the injection level).

Test 1: CE - CM current emission measurement (frequency domain) on selected cable bundles.

Test 2: Sine wave injection on selected cables bundles. Injection level: 6 dB higher than the emissions measured on the bundle.

- Frequency range: 10 kHz – 50 MHz
- The required frequency range shall be covered by manually testing at certain spot frequencies

2. CS simulating RS on the Cryo Harness (ref. [RD1], § 6.3.1.1)

Test method: Sine wave injection CM on cryo harness bundles.

- Frequency range: 14 kHz – TBD MHz
- Injection level: 2 mA_{rms}
- Measurement accuracy is expected to decrease above 50 MHz

3. RS on HPLM EQM in cold conditions (ref. [RD1], § 6.3.1.2)

Test method: RS E-field injection

- Frequency range: 14 kHz – 18 GHz
- Above 30 MHz, test with horizontal and vertical antenna polarization.
- Injection level: 2 V/m, 1 m distance, 30 % amplitude modulation by 1 kHz square wave, 18 V/m or 10 V/m in RF notches
- Calibration of the E-field levels will be performed in the EMC facility.

Instruments AIT Meeting - EQM/PFM Testing

EMC test approach (5)

4. RS on HPLM EQM in cold conditions (ref. [RD1], § 6.3.1.2)

Test method: RS AC H-field injection

- Frequency range: 30 Hz - 50 kHz
- Injection Level: 140 dB_{pT} sine wave, distance tbd.
- Calibration of the H-field level will be performed in the EMC facility.
- The required frequency range shall be covered by manually testing at certain spot frequencies.

5. RS on HPLM EQM in cold conditions ([RD1], § 6.3.1.2)

Test method: RS DC H-field injection

- Injection Level: 160 dB_{pT}, distance tbd.
- Calibration of the H-field level will be performed in the EMC facility.

The general arrangements necessary for the RS tests are shown in Fig 1 below.

References:

[RD1]: HP EMC Control Plan, HP-1-ASPI-PL-0038, issue 3, 27.05.02

[RD2]: HP EMC Specification, HP-1-ASPI-SP-0037, issue 3, 14.06.02

Instruments AIT Meeting - EQM/PFM Testing

EMC test approach (6)

- E/H field sources which radiate into CVV
 - Low frequencies (< 10 kHz): fields from sources located outside CVV (as e. g. from solar array) decrease with $1/r^3$ (near field), dominant sources are FPU's \Rightarrow instrument auto-compatibility test sufficient.
 - Medium frequencies (10 kHz to 100 MHz): noise propagation via parasitic currents in the cryo harness dominates \Rightarrow RS test: common mode noise on cryo harness by radiation onto CVV (ISO approach). RS test is performed using standard external antennas with CVV cover being closed and providing the appropriate thermal background to verify the instrument EMI compatibility.
 - High frequencies (> 100 MHz): dominant sources are HIFI LOU (X-band TTC-RF is off during HIFI operation), top opening is not considered as a critical noise coupling mechanism \Rightarrow HIFI auto-compatibility test is considered to be sufficient, plus RS test as for medium frequencies.

Instruments AIT Meeting - EQM/PFM Testing

EMC test approach (7)

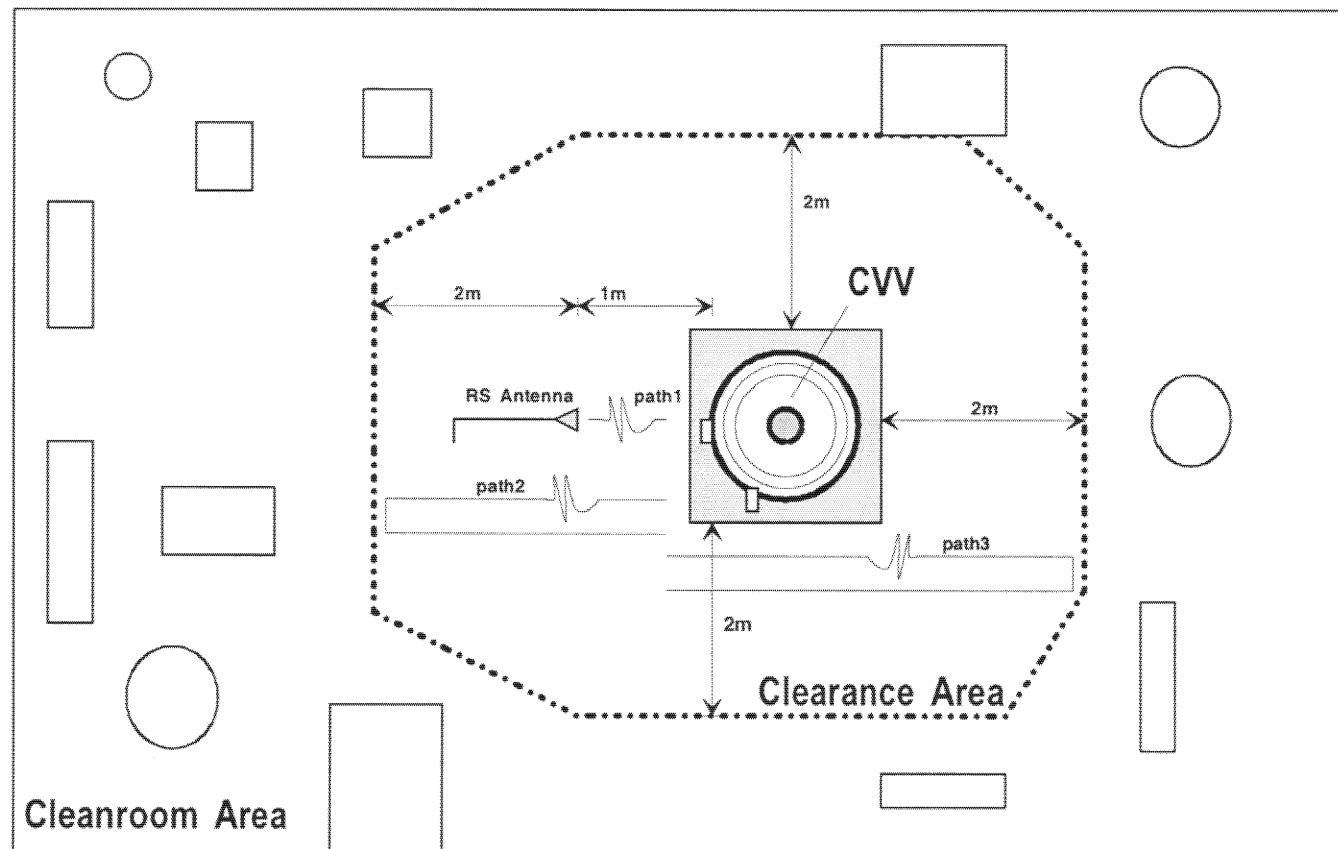


Fig1.: General Arrangement of the HPLM Inside the Integration Facility during RS tests

Instruments AIT Meeting - EQM/PFM Testing

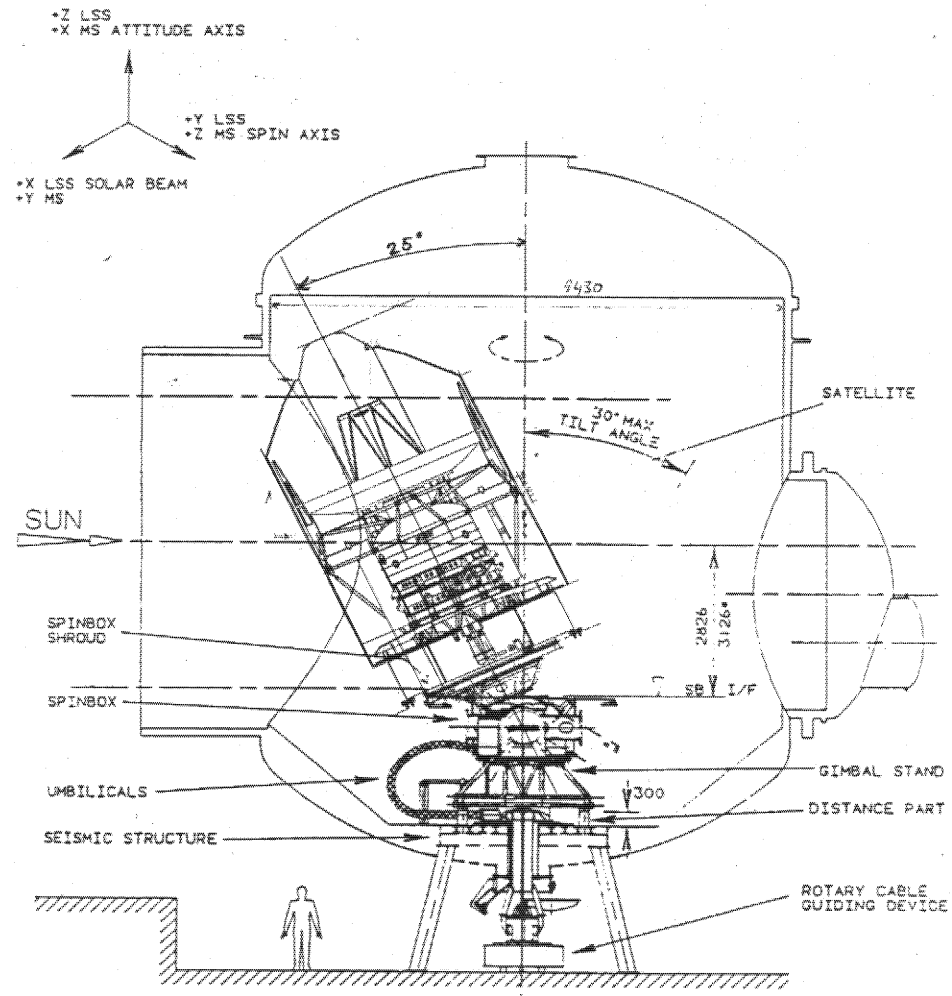
TB/TV test approach (1)

- Thermal balance
 - Confirmation of adequacy of thermal analysis and temperature prediction models
 - Verification of external vent line performance (delta p, nozzle)
- Thermal vacuum
 - Verification of proper function and performance of payload with all sensors operational
 - Verification of performance of active and passive thermal control
 - Complete system level qualification/acceptance test
- Major constraints
 - Test time limited by Helium II level
 - Tilting

Instruments AIT Meeting - EQM/PFM Testing

TB/TV test approach (2)

- Detailed inputs needed from instruments
 - Test requirements, test flow, sequences, breakpoints
 - Test constraints (temperature requirements, temperature stability requirements)
 - Test time



Instruments AIT Meeting - EQM/PFM Testing

IST approach

- See presentation of ESTEC

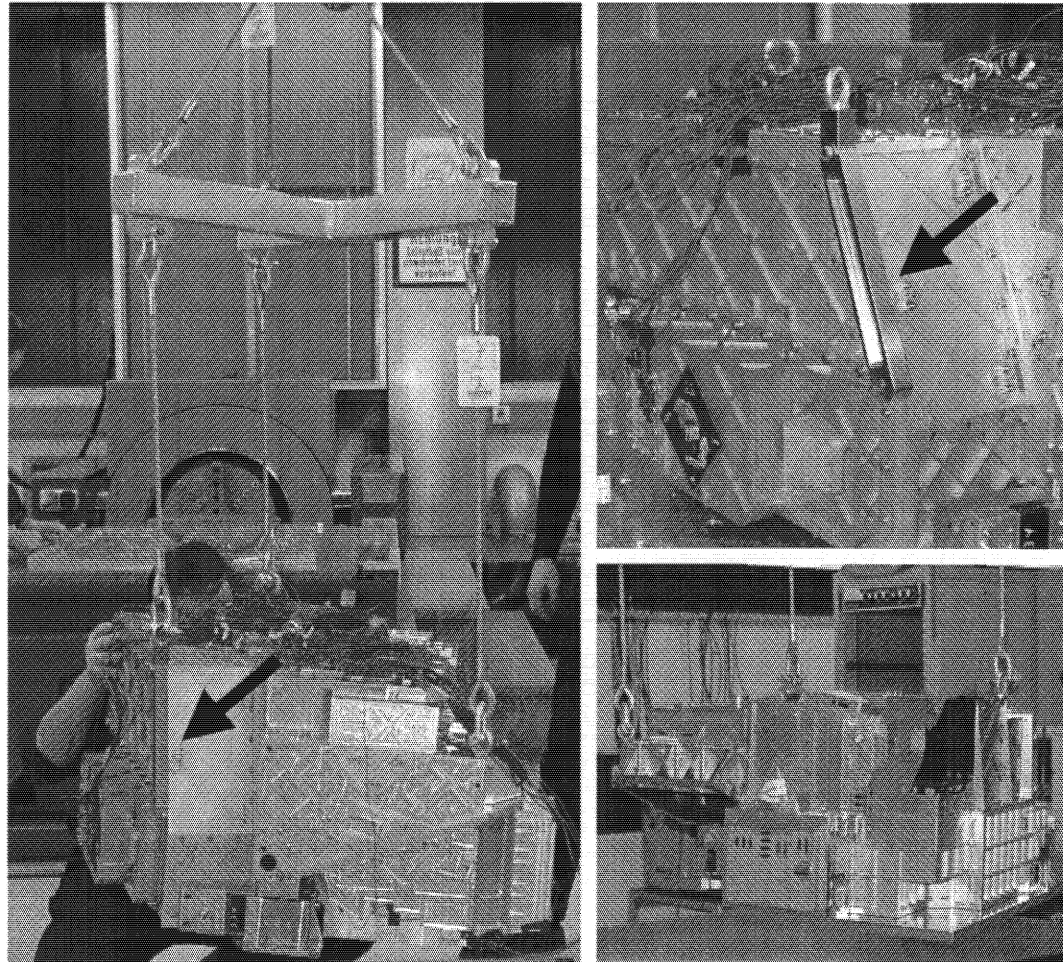
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FPU Integration Sequence

Josef Schubert
MPE

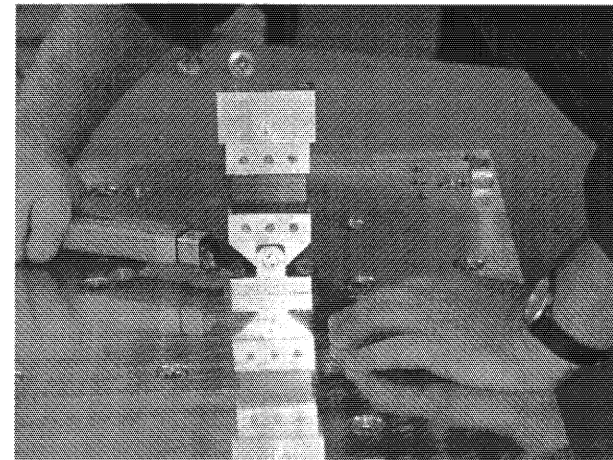
FPU Hoisting Tools

- PACS Hoisting Tool with elongated eyelet at the spectrometer side (red tagged item)
- For a slow let down of the PACS FPU a fine drive for the crane is needed



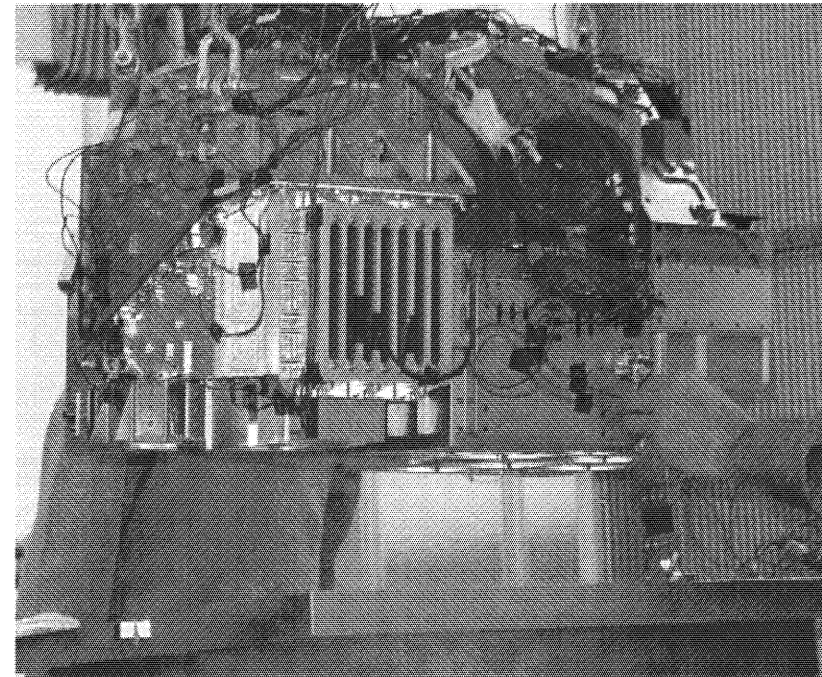
FPU Integration Sequence on Optical Bench

- Prior to the PACS FPU integration, the PACS FPU-one axis suspension feet needs to be mounted on the optical bench
- Two dowel pins (SST, diameter 12mm, H7) and shimming plates to be placed into the pin holes of the optical bench
- Tightening torque for all M8 mounting screws is 23Nm (@ RT)



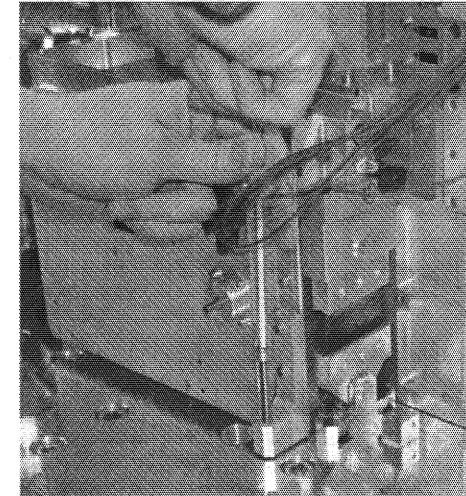
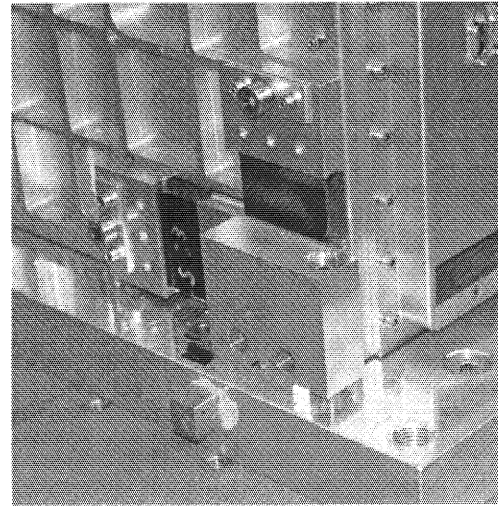
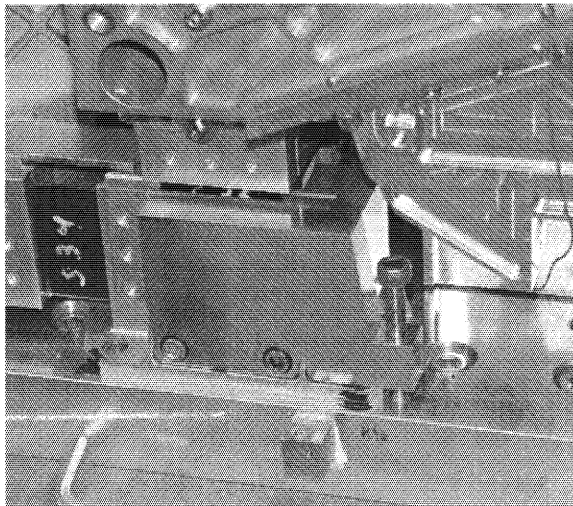
Lessons learned during STM-FPU integration (I)

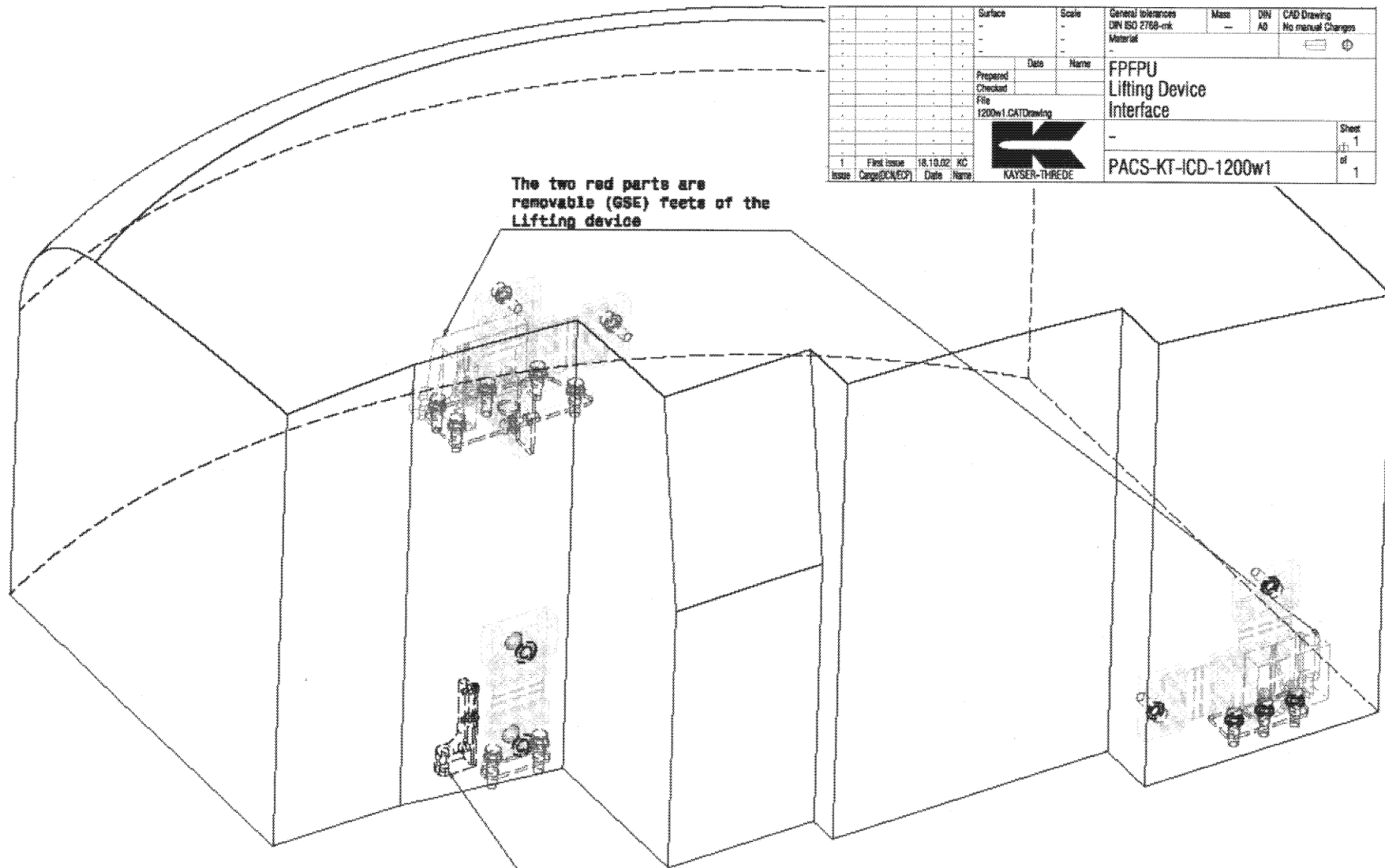
- Hoisting device needs to have an adjustable tightrope length (threaded rod). Balancing of PACS-FPU can not be done with counter weights on the hosting device.
- Mount guiding tool for FPU integration via crane under discussion. This would insure, that the one axis suspension feed cannot be damaged during lowering of the FPU
 - > two additional threads within the optical bench needed.



Lessons learned during STM-FPU integration (II)

- Elongated pin hole in the two axis suspension feet is not necessary; tolerances are within the elastic range of the CFRP plates
- Now shimming plates (nominal 3mm) below the PACS feet might be critical; only 1 mm distance left between PACS and optical bench
- Lifting tool was successfully tested (for emergency only)





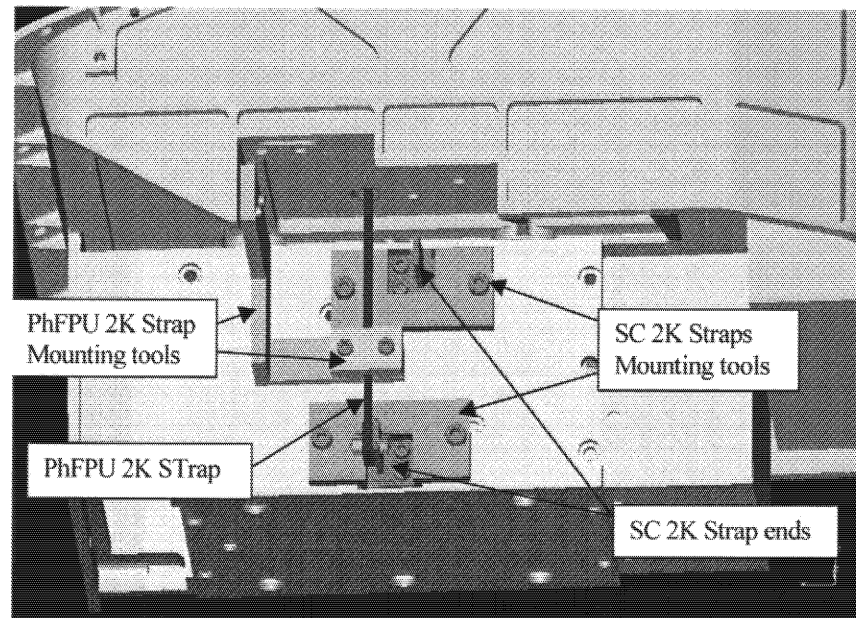
The two red parts are removable (GSE) feet of the Lifting device

The fixed lifting device is part of the Housing Structure and will not be removed but decoupled from the Optical Bench (the lifting screw will be removed)

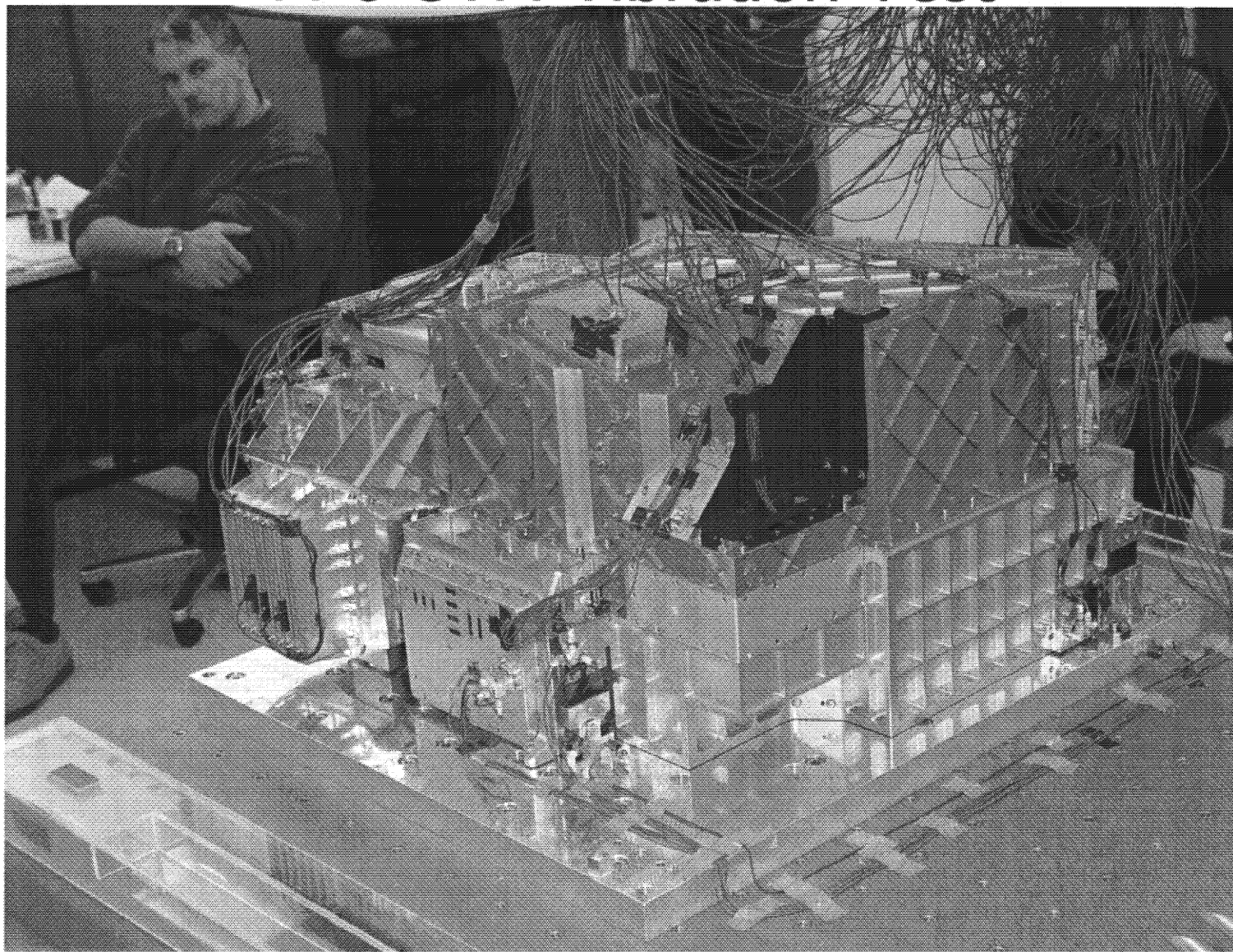
Surface	Scale	General tolerances	Mass	DIN A0	CAD Drawing
-	-	DIN ISO 2768-mk	-	-	No manual Changes
-	-	Material	-	-	
Prepared	Date	Name	FFPJU		
Checked			Lifting Device		
File			Interface		
1200w1.CATDrawing			-		
					Sheet
1	First Issue	18.10.02	KC		1
Issue	Change/ECN/ECF	Date	Name		of
					1
				PACS-KT-ICD-1200w1	

FPU Integration Constrains

- In the case the short circuit connectors are removed from the FPU connector panels, test personal needs to be grounded during handling
- Cooling traps to the 2K cooler I/F are fragile. PACS/CEA will provide a integration tool.

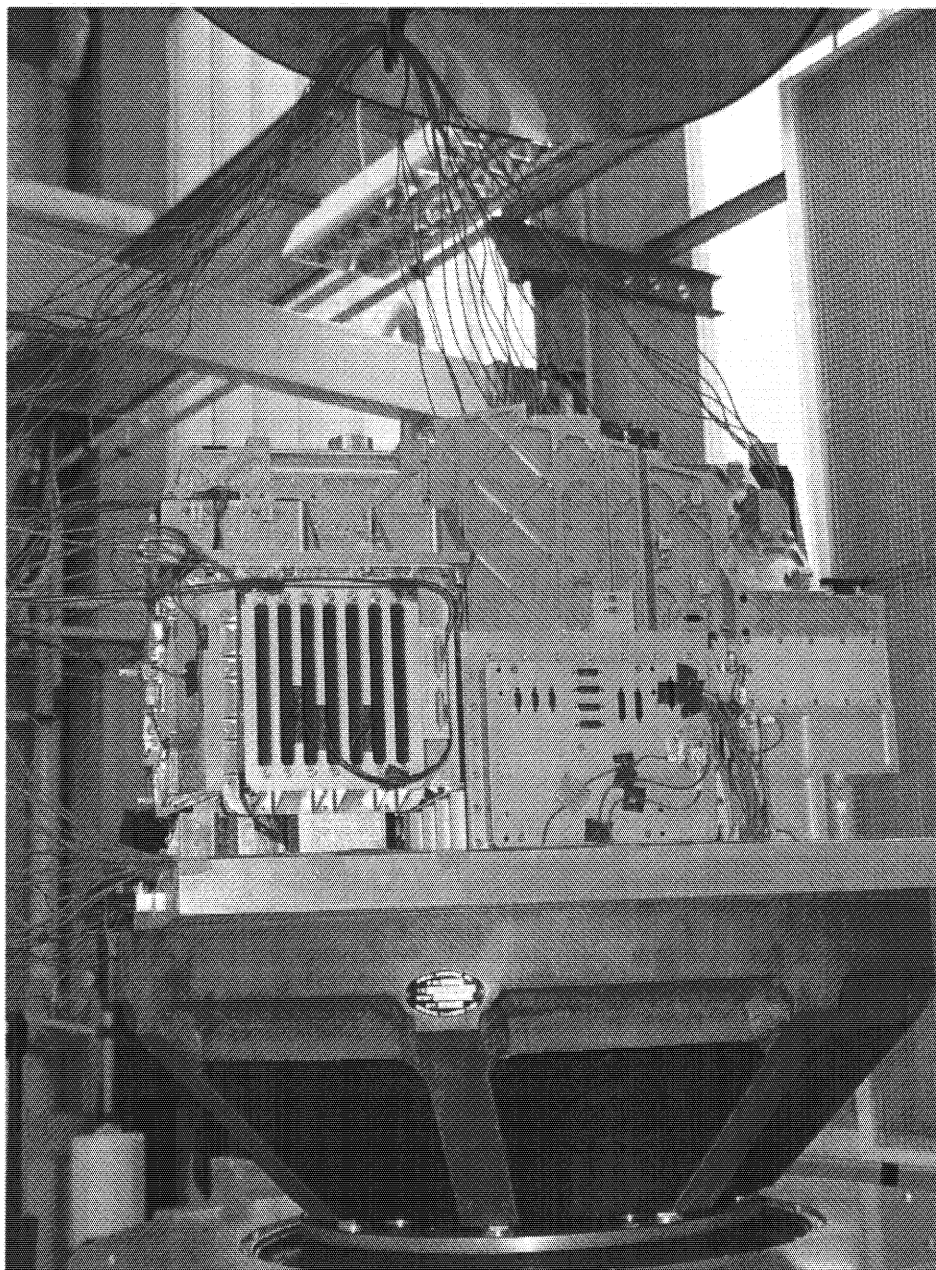


FPU STM Vibration Test



MPE/J.S.

FPU STM Vibration Test



MPE/J.S.

FPU STM Vibration Test

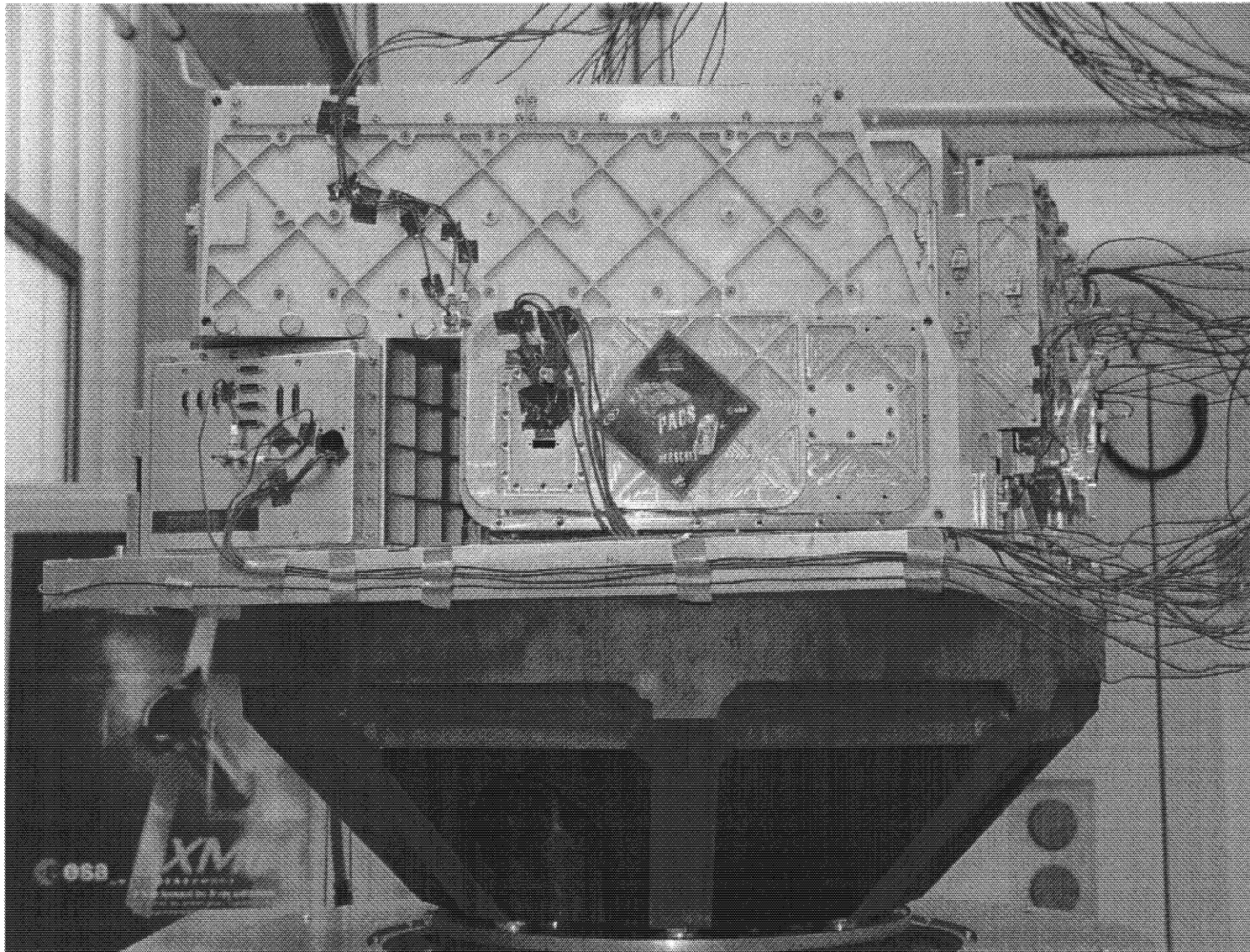
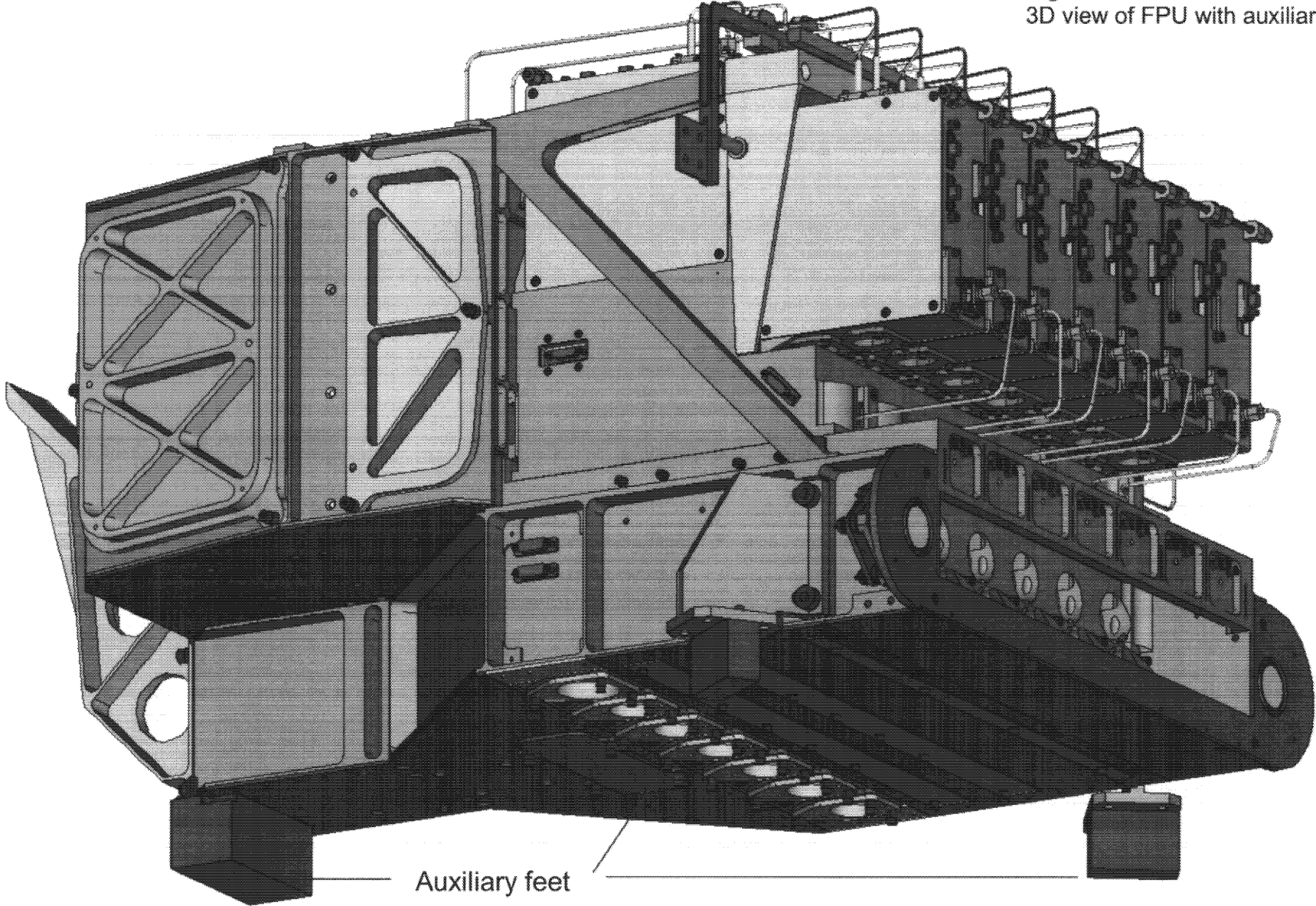
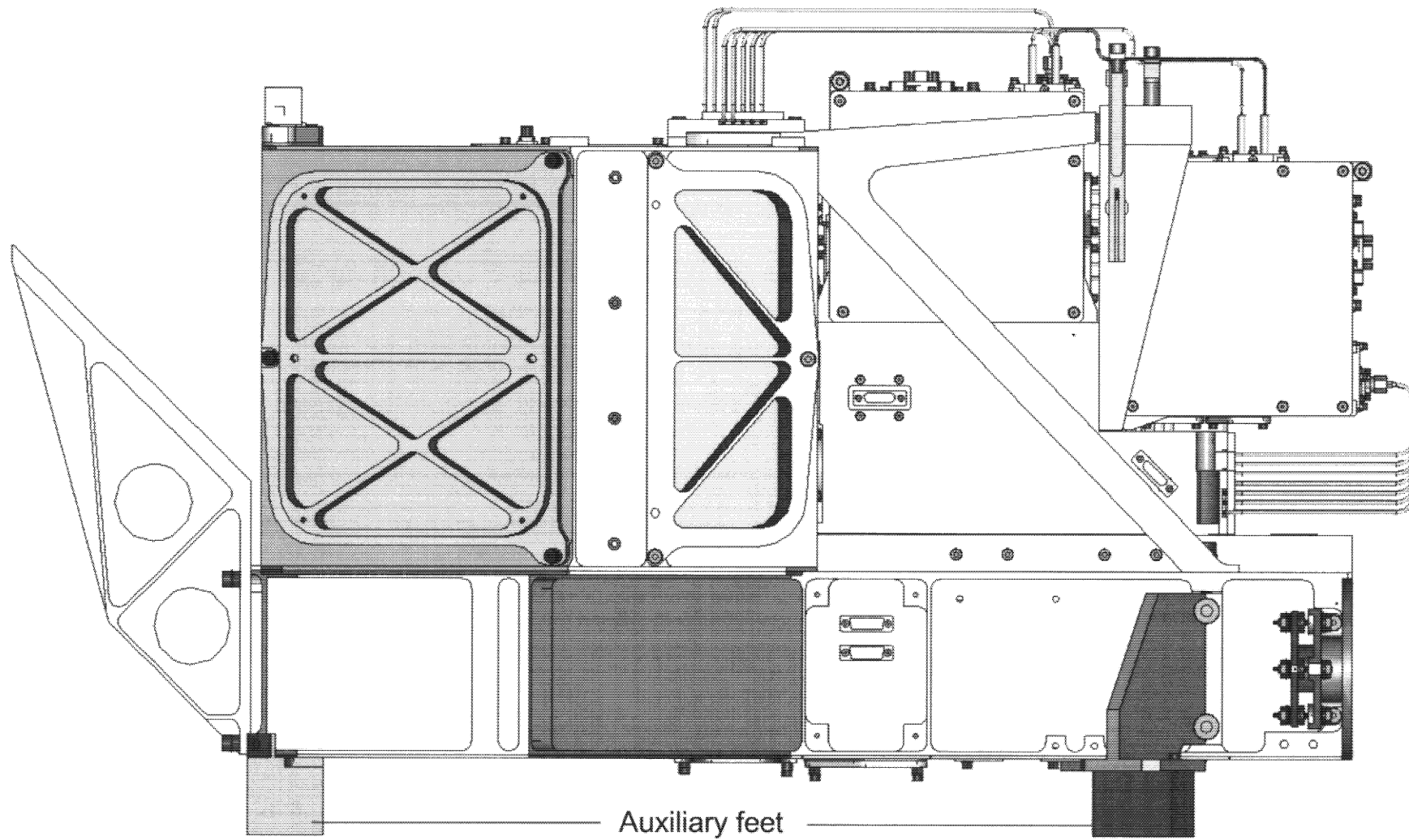


Figure 1
3D view of FPU with auxiliary feet installed



ANNEX 3

Figure 2
Side view of FPU with auxiliary feet installed



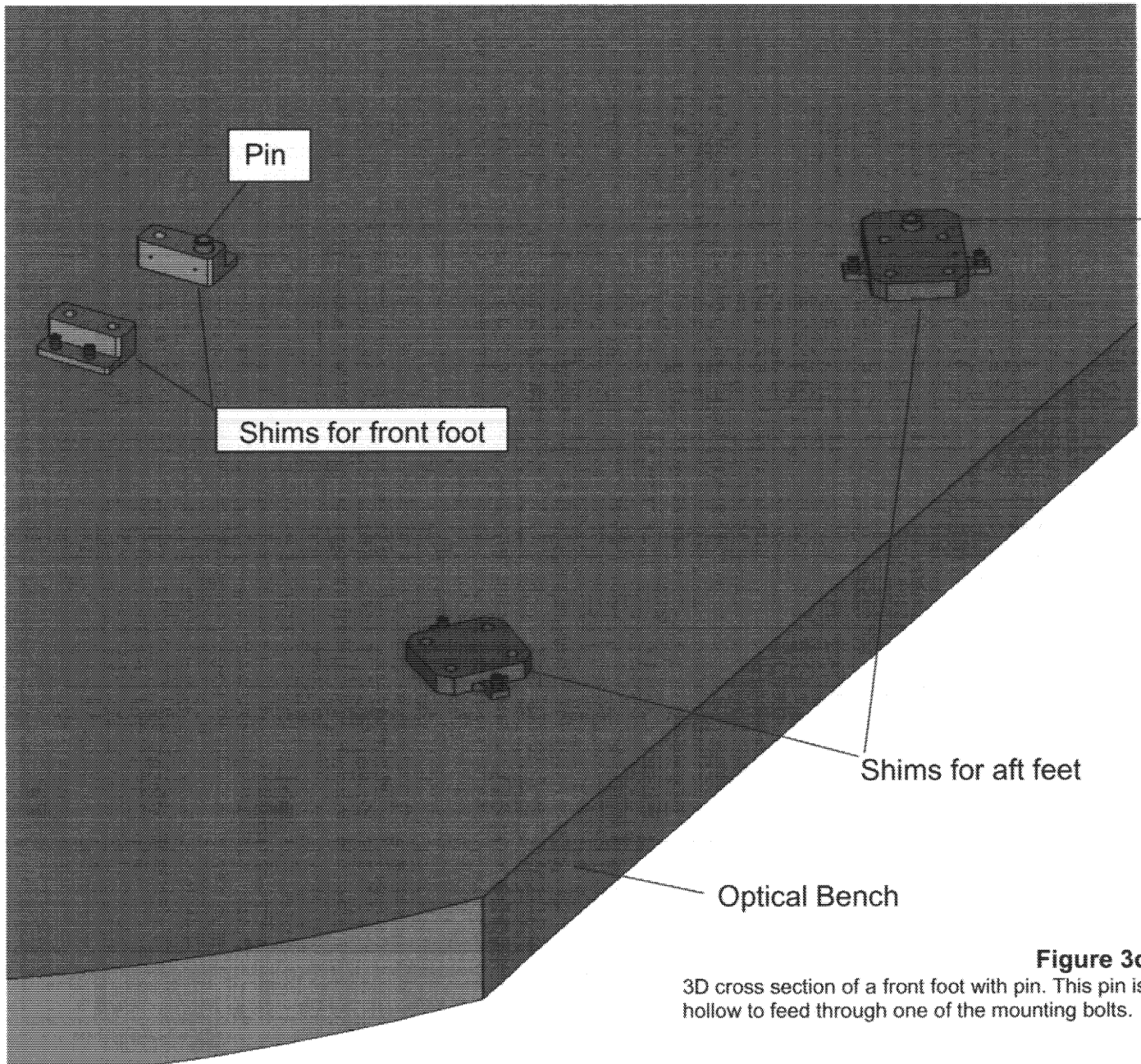
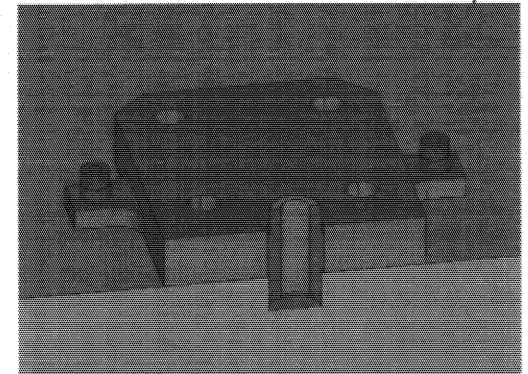


Figure 3a
Shims on optical bench

Pin

Figure 3b
3D cross section of a aft foot shim with pin



Shims for aft feet

Optical Bench

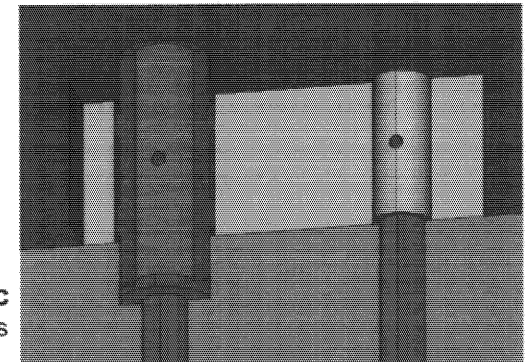


Figure 3c
3D cross section of a front foot with pin. This pin is hollow to feed through one of the mounting bolts.

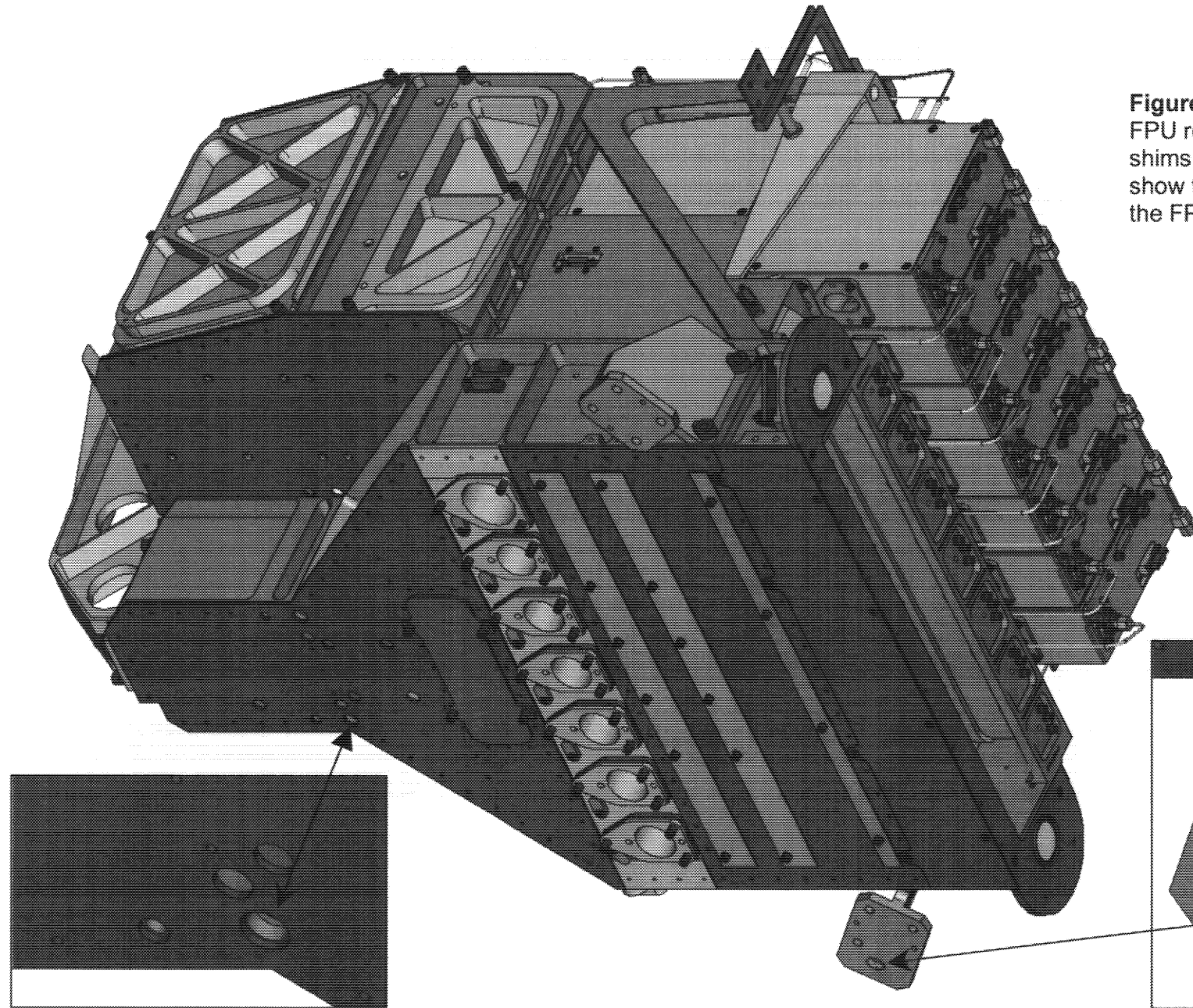
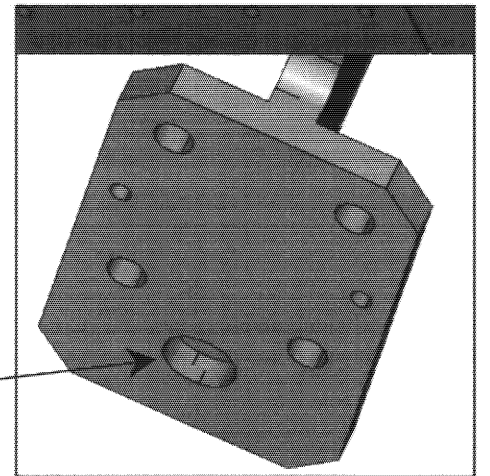


Figure 4
FPU ready for mounting onto the shims on the OB. The detail sketches show the circular resp. oblong hole in the FPU feet for the pins.



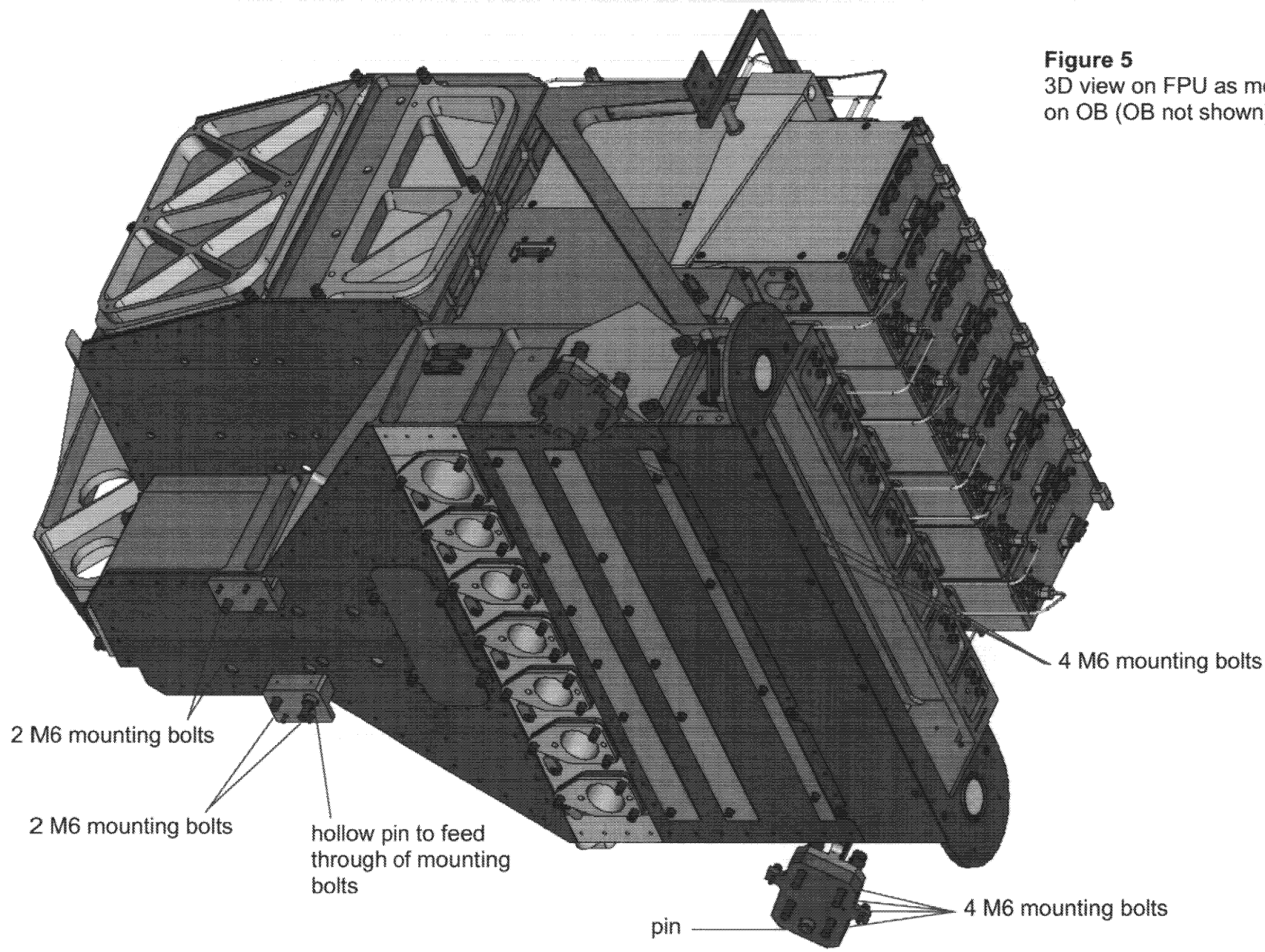


Figure 5
3D view on FPU as mounted
on OB (OB not shown)

2 M6 mounting bolts

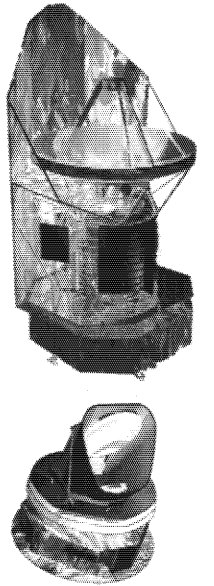
2 M6 mounting bolts

hollow pin to feed
through of mounting
bolts

4 M6 mounting bolts

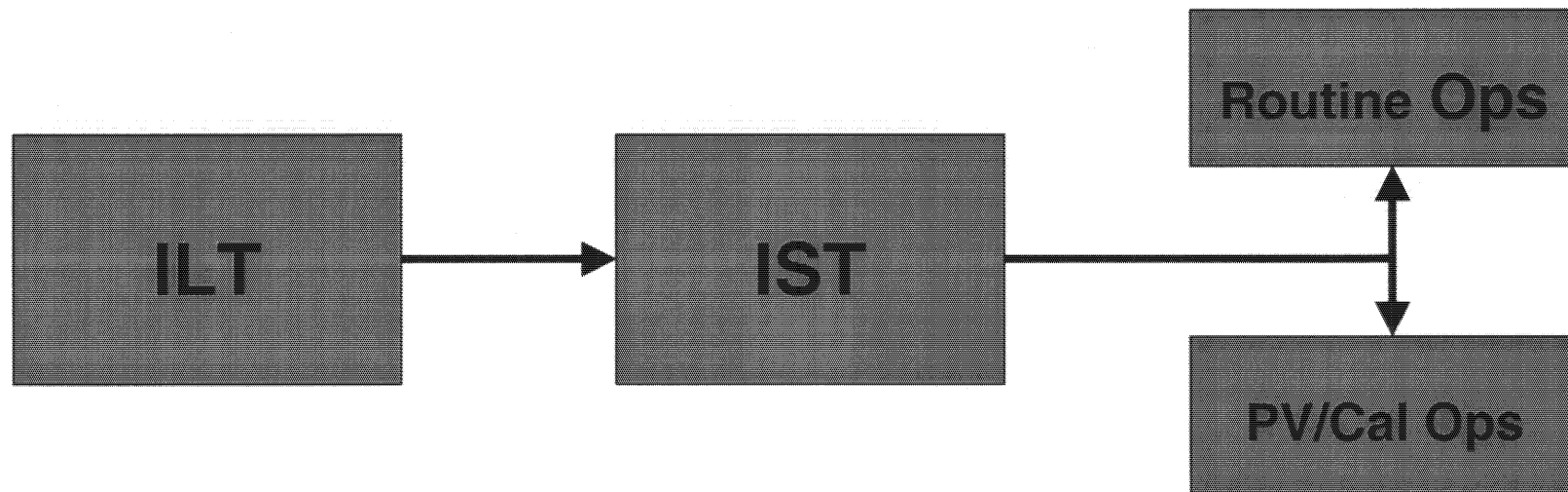
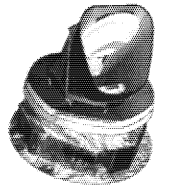
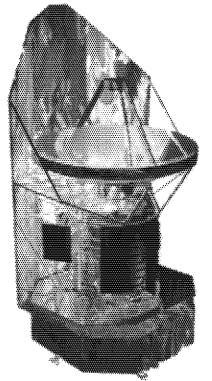
pin

4 M6 mounting bolts

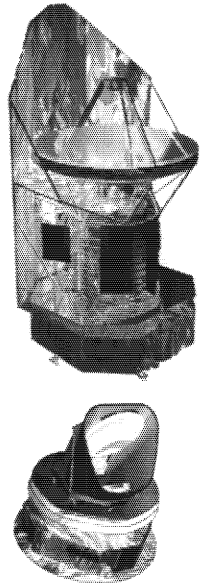


Approach to ISTs

21 January 2003

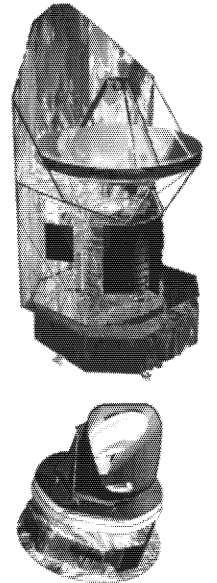


Smooth Transition Requirement



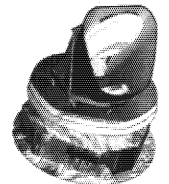
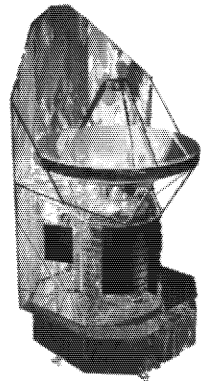
ILTs

- **Performed individually at instrument level before delivery**
- **To include functional, performance and reference tests of instruments**
- **Make use of HCSS and EGSE-ILT based on SCOS 2000**
- **During ILT, EGSE-ILT interfaces the HCSS to get the “Observation Plan” and ObsID requested for the test.**



ISTs

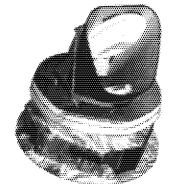
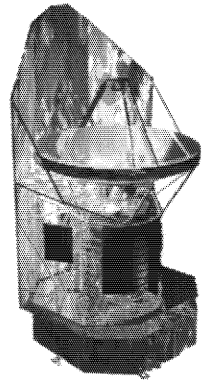
- To verify correct operation of the full integrated spacecraft in a series of representative mission scenarios including failure cases
- To be performed on the AVM (Herschel and Planck), STM/CQM (Planck only) and PFM (Herschel and Planck)
- ISTs to combine procedures developed and debugged at SVM, PLM and Instrument level
- IST to include some Instruments performance tests (Herschel PFM)



Operations(1)

From: Reference Mission Scenario (Herschel)

- **Commanding of the satellite (spacecraft and instruments) is carried out exclusively by the Mission Operations Centre (MOC) located at ESOC.**
- **For Herschel an Operational Day (OD = 24 hours) has been defined as basic planning unit for the operational phase.**
- **Each OD can be divided into: DTCP (i.e visibility period of about 3 hours) and autonomy period (remaining 21 hours)**
- **HSC to submit to MOC an Observation Plan covering about 3 weeks**
- **From the Observation Plan, MOC to derive a detailed Schedule of activities and the related MTL for each OD.**

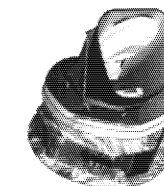
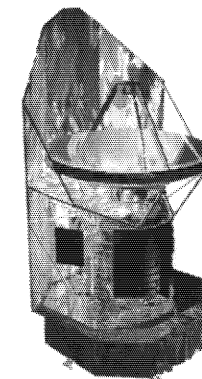


Operations(2)

From: Reference Mission Scenario (Herschel)

Some activities during DTCP

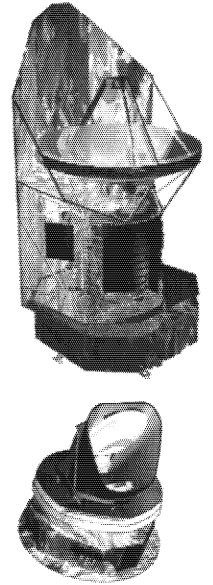
.....	
P + 2 min	Request downlink of events, recorded HK and recorded Science in this order of priority.
.....	
P + 10 min	Evaluate recorded HK and events data, start downlink of science data
.....	
P + 1 hour	Update on-board schedule (top-up, normally for 24 h)
.....	



Operations (3)

During the Operation (routine) phase:

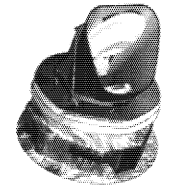
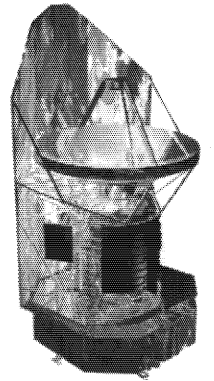
- The HSC shall provide in advance the Observation Plan
- There is no real time involvement of the HSC
- The MOC can transfer science data to the HSC after several hours
- All commanding and recovery actions shall be controlled by the MOC



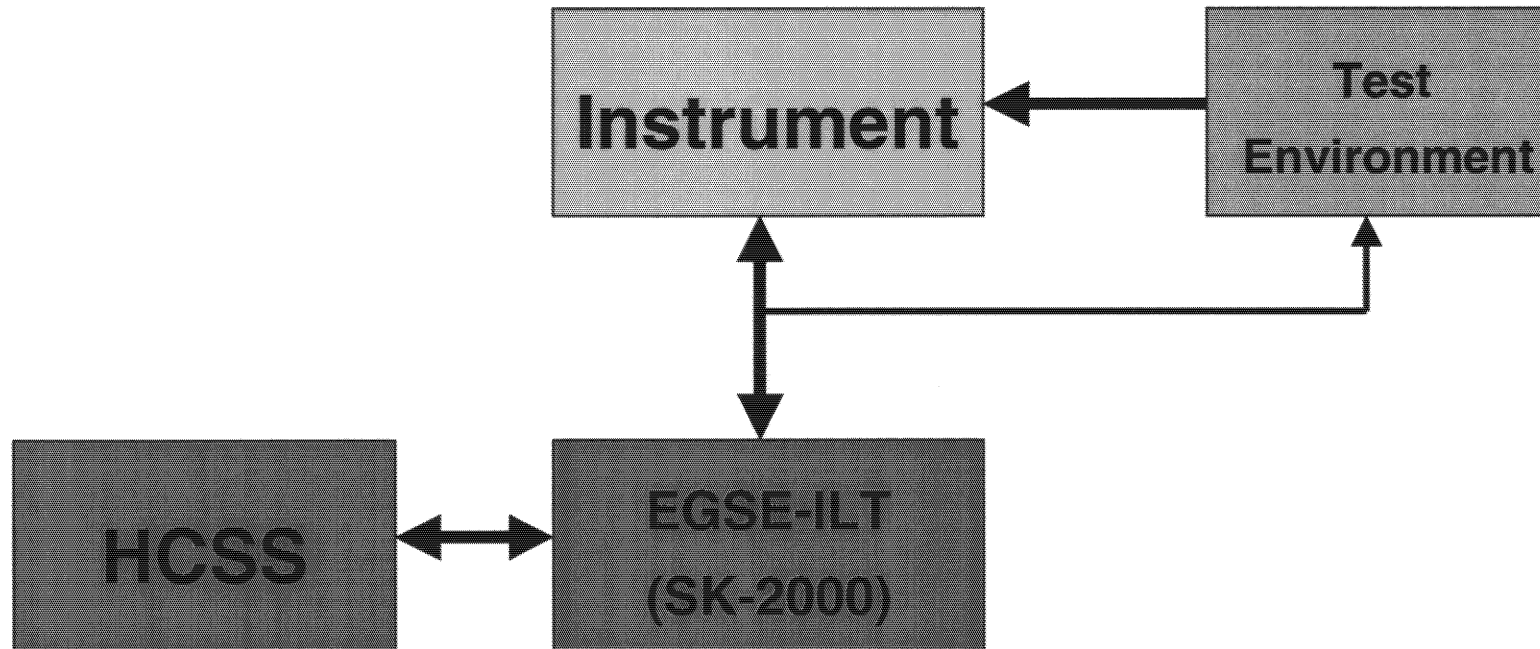
Operations (4)

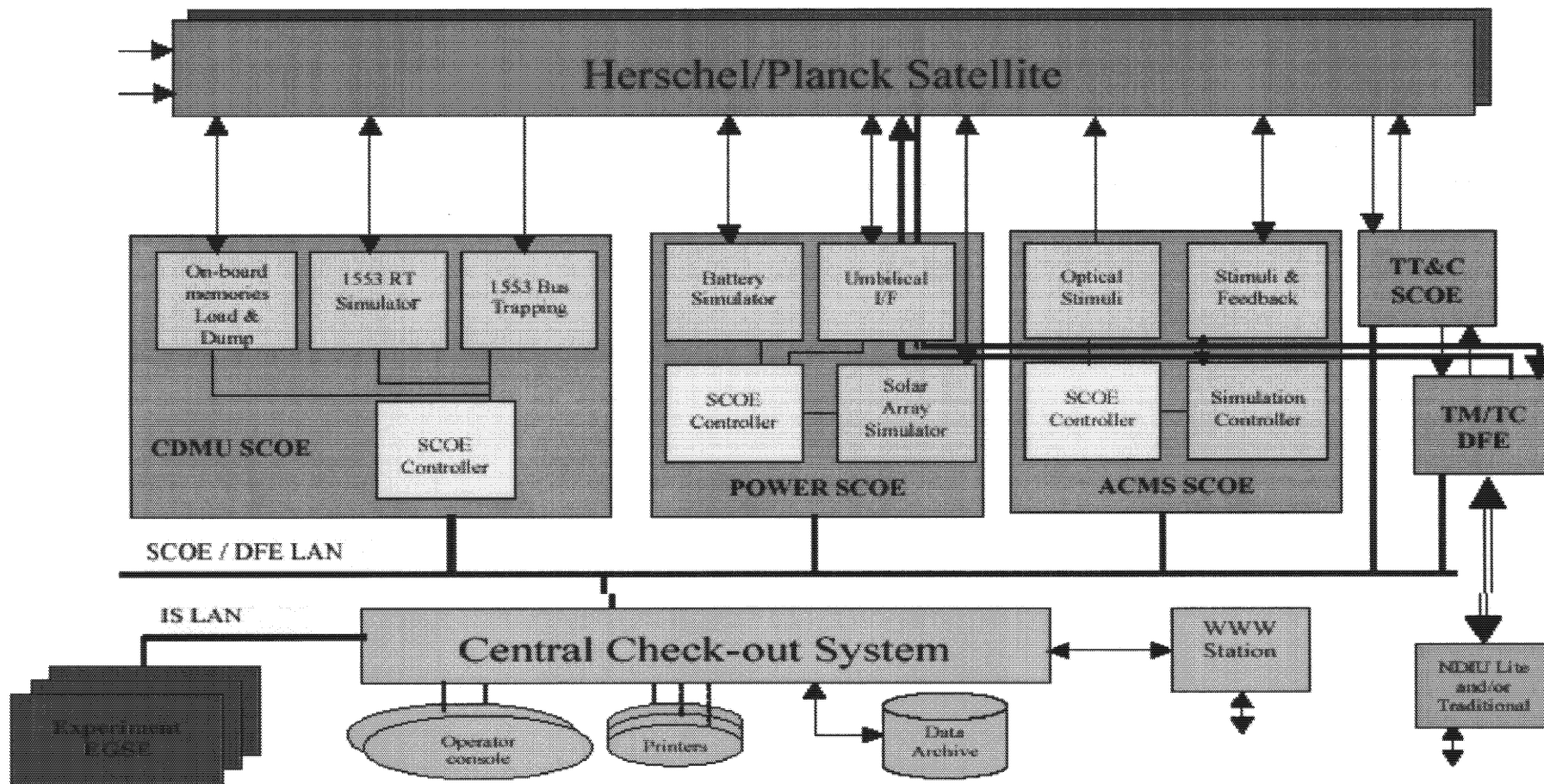
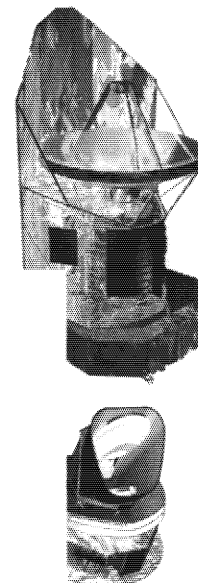
During the Calibration/PV phase (may be in T.O.):

- An ICC is installed in the MOC
- 10 hrs visibility per day looks possible
- Real time interaction ICC/MOC might be requested (unclear)

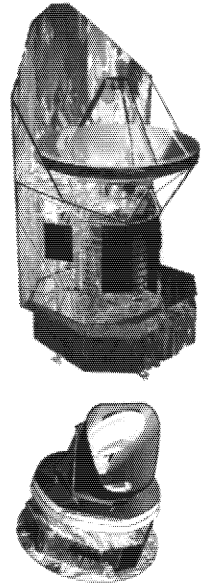


Set-up for ILT (Herschel)

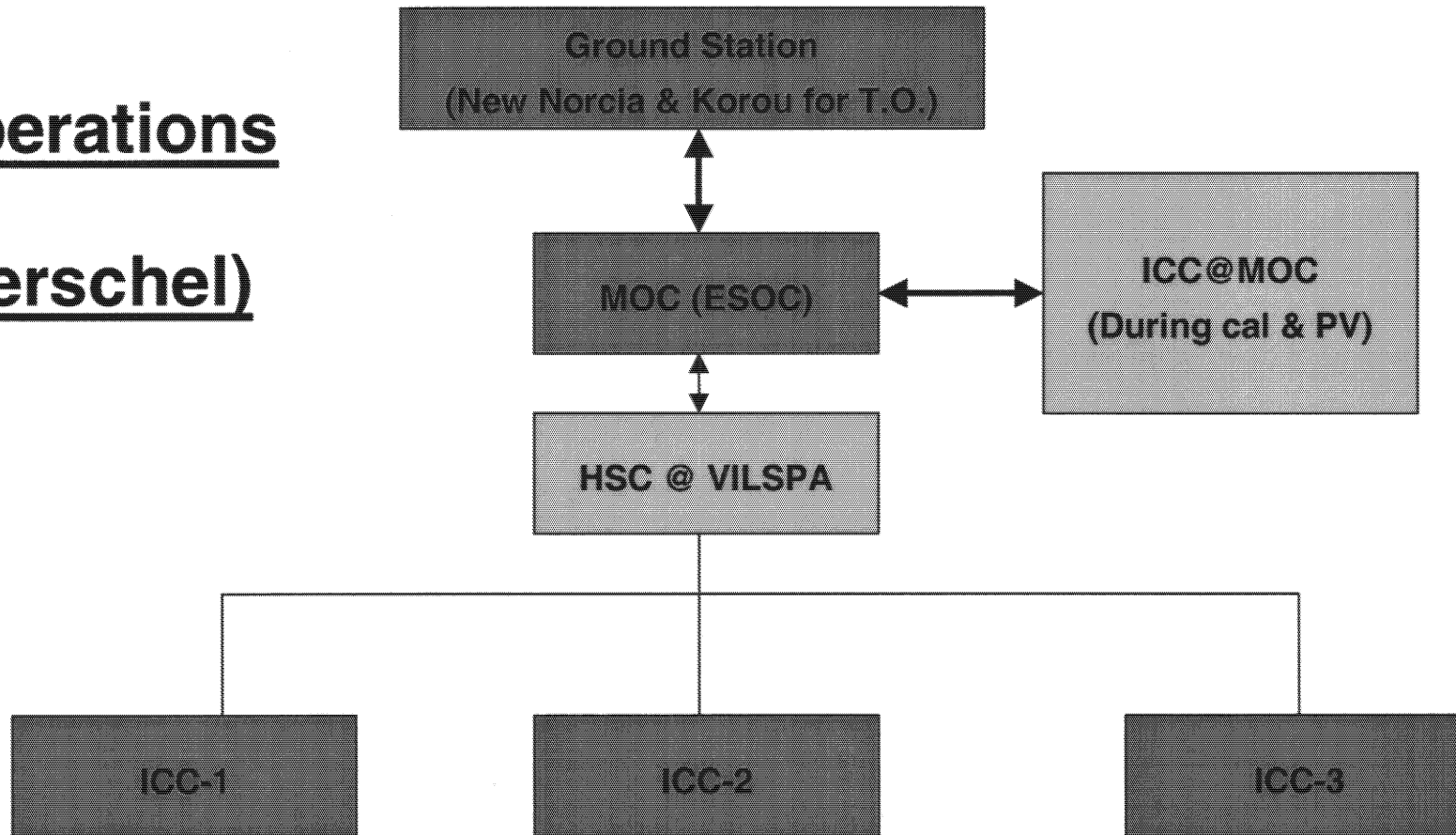


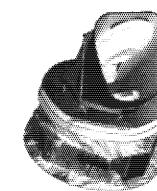
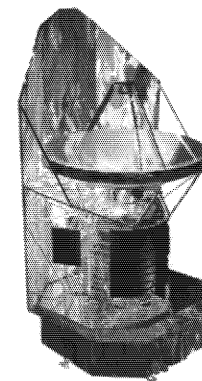


Set-up for ISTs



Operations
(Herschel)



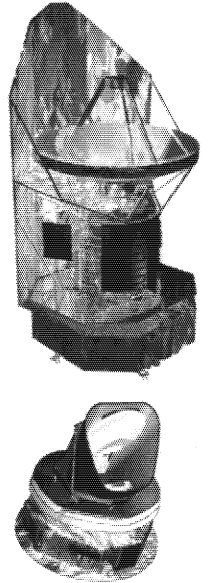


Utilisation of the I-EGSE at System Level

During system level activities, 3 ways of operating the I-EGSE are considered:

- Mode-1: I-EGSE OFF (or unavailable)
- Mode-2: I-EGSE in listening mode i.e. one way communication only from CCS to I-EGSE to dump Instruments HK and Science data
- Mode-3: I-EGSE involved in real time testing under the control of the CCS

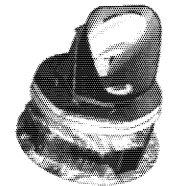
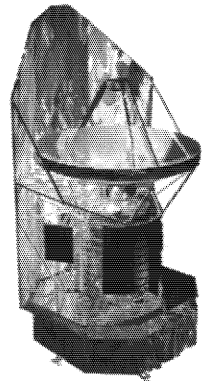
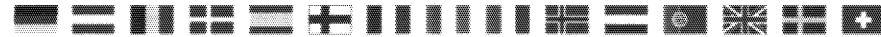
Regardless the selected mode, the CCS retains the control of the test activity. The I-EGSE cannot uplink commands to the spacecraft.



Approach to IST (1)

- Initial running of IST will require debugging of procedures and AIT SW with flexibility to fix quickly minor bugs
- Context saving and re-start may be normal practice (no night shift)
- ISTs to run initially with pre-defined Observation Plan and associated MTL both prepared in advance and available in the CCS.
- Failure cases can also be tested.
- It might be necessary to re-use several time the same Observation Plan
- **In this configuration the I-EGSE shall be in listening mode (Mode-2)**

A successful IST in this configuration ensures smooth transition between IST and routine operations phase with the CCS replacing the MOC.

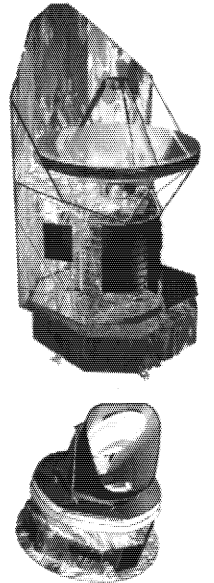


Approach to IST (2)

- IST also requires (Herschel) Instruments verification and consideration of the activities of the ICC@MOC during calibration and PV phase (T.O.)
- ISTs to run initially with pre-defined Observation Plan and associated MTL both prepared in advanced and available in the CCS.
- Real time involvement of the I-EGSE is requested in order to:
 - Evaluate science data
 - Provide updated Observation Plan as needed
 - Validate ground SW (HCSS), QLA, RTA
- **In this configuration the I-EGSE shall be involved in real time testing (Mode-3)**

A successful IST in this configuration ensures smooth transition between:

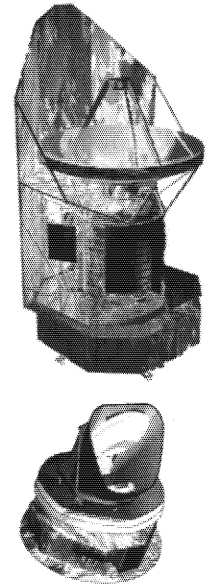
- IST and PV/ calibration phase with the CCS replacing the MOC and
- ILT and IST for all Instrument data processing



Approach to IST (3)

Interfaces required to support IST:

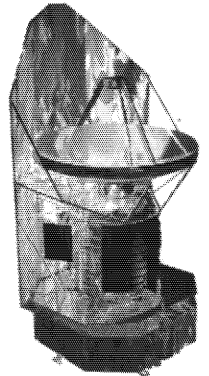
- EGSE I/F Requirements Spec H-P-1-ASPI-IS-0121 to be completed with RC/RM for I-EGSE and Observation Plan
 - normal work to be completed by end February (TBC)
- TC history files
 - already implemented in the CCS and I-EGSE



Approach to IST (4)

On the whole smooth transition is supported by:

- Overall approach to IST as mentioned above
- Established EGSE functionalities and ICDs
- Common SDB
- EGSE (CCS and I-EGSE) and MOC based on SK 2000



Approach to IST (5)

What's next:

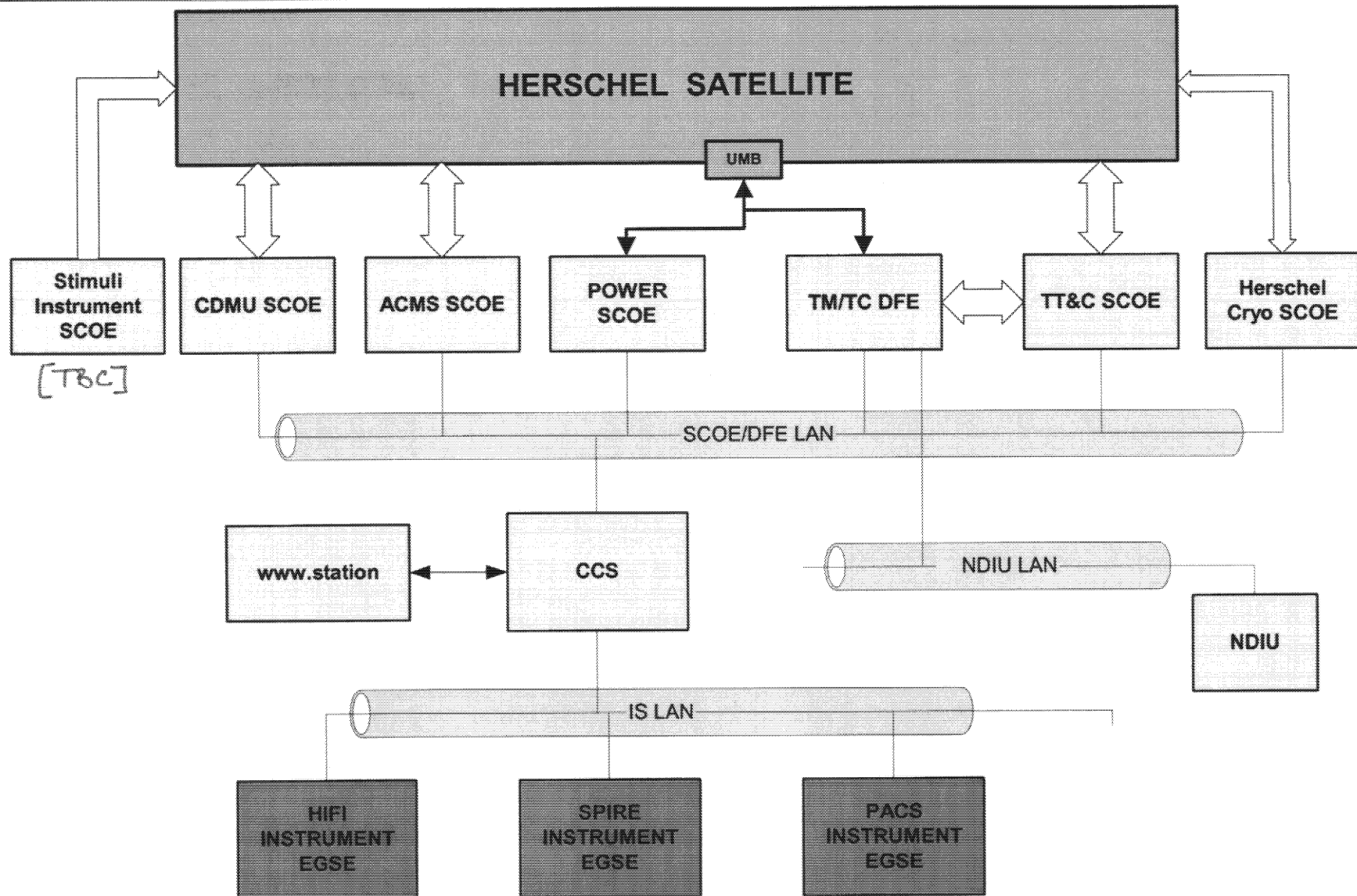
Detailed implementation of the IST to be defined in:

- **Herschel IST Specification**
- **Planck IST Specification**

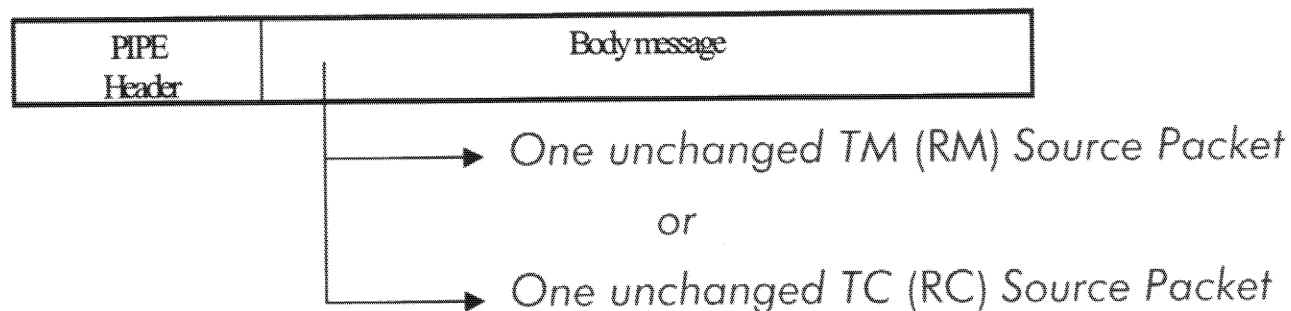
both documents to be issued by Prime

OVERALL HERSCHEL S/C Test Configuration

21-JAN-2003



▼ PIPE protocol allows to exchange Packets between CCS and EGSE items connected via LAN. The protocol is structured in such a way that *TM Source Packets* and *TC Source Packets* are transferred without any changes (Body Message). This is achieved by the attachment of an information header (*PIPE header*) containing additional information required for proper routing and processing of the Packets.



▼ The main principle of PIPE protocol is to consider each SCOE as an Onboard equipment:

- ↳ Each SCOE receive TC packets from CCS (called **RC** - **R**emote **C**ommand)
- ↳ Each SCOE transmit Telemetry Packets to CCS (called **RM** - **R**emote **M**essage)

Refer to H-P-583

▼CCS shall receive from each I.EGSE at least one RM Packet every 60 seconds. (=> TM)

The following Remote Messages shall be foreseen :

→ Periodic RM packets containing vital data measured/acquired by each I.EGSE (if needed)

AND/OR

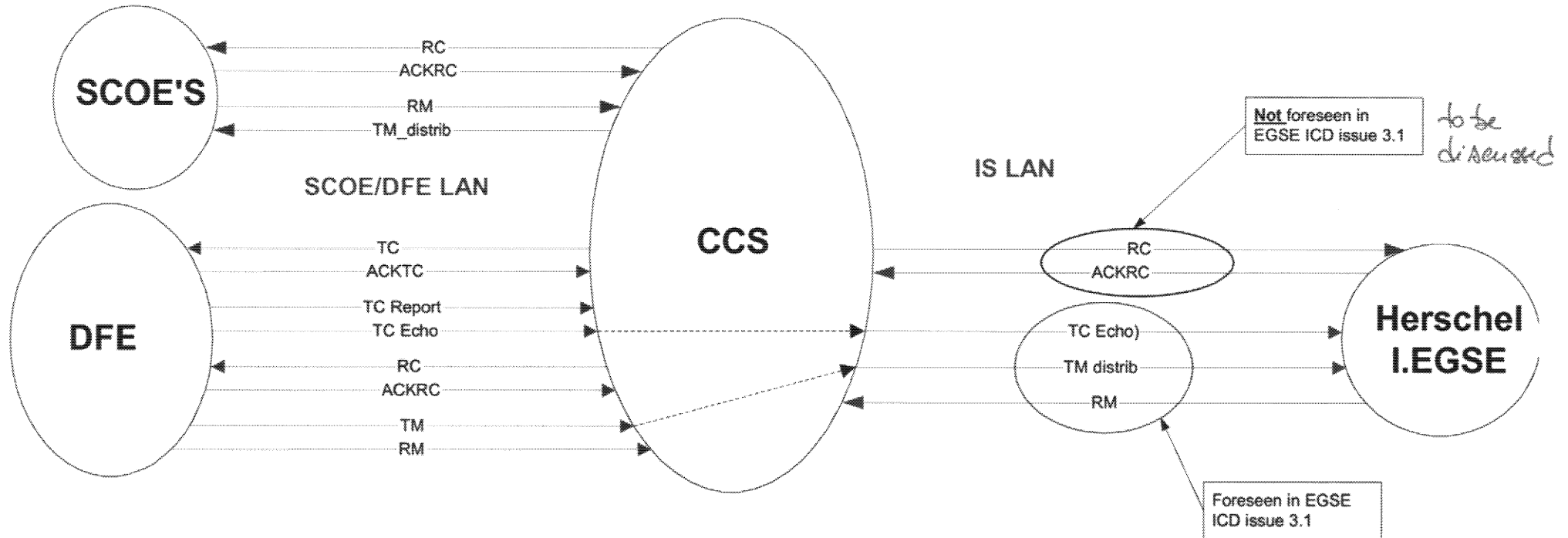
→ Asynchronous RM packets containing special events /errors/warning notification (if needed)

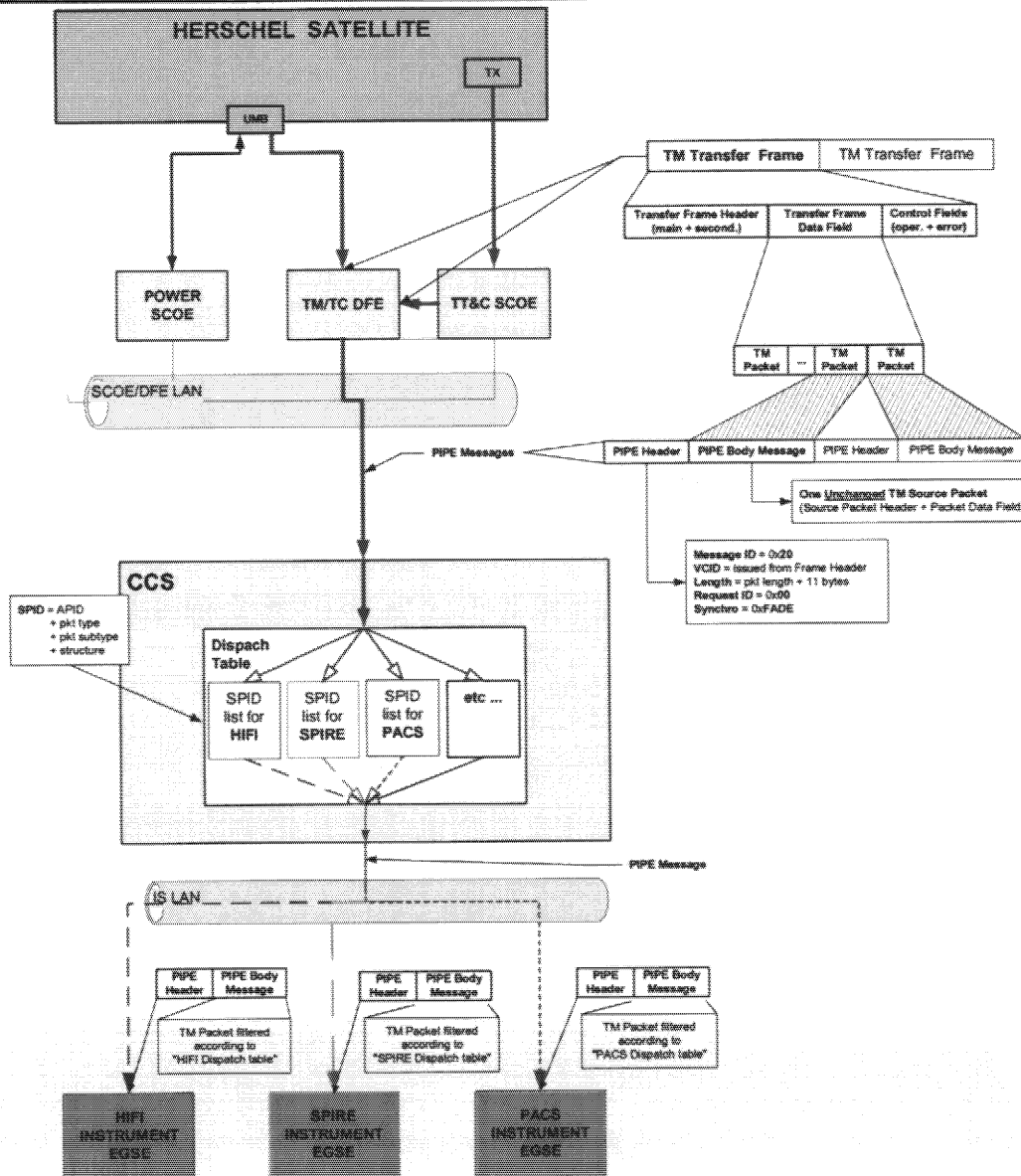
AND/OR

→ Alive RM Packets (empty packet used to control the link between CCS and I.EGSE)

▼CCS will distribute to Each I.EGSE TM Source Packets according to the dispatch table.
(The dispatch table contains the list (combination of APID/type/sub-type/structure) of TM Packet to be send to I.EGSE)

▼Each I.EGSE shall receive from CCS TC Echo Packets.
TC Echo Packets contain the re-constructed TC Source Packet sent by TM/TC to S/C)

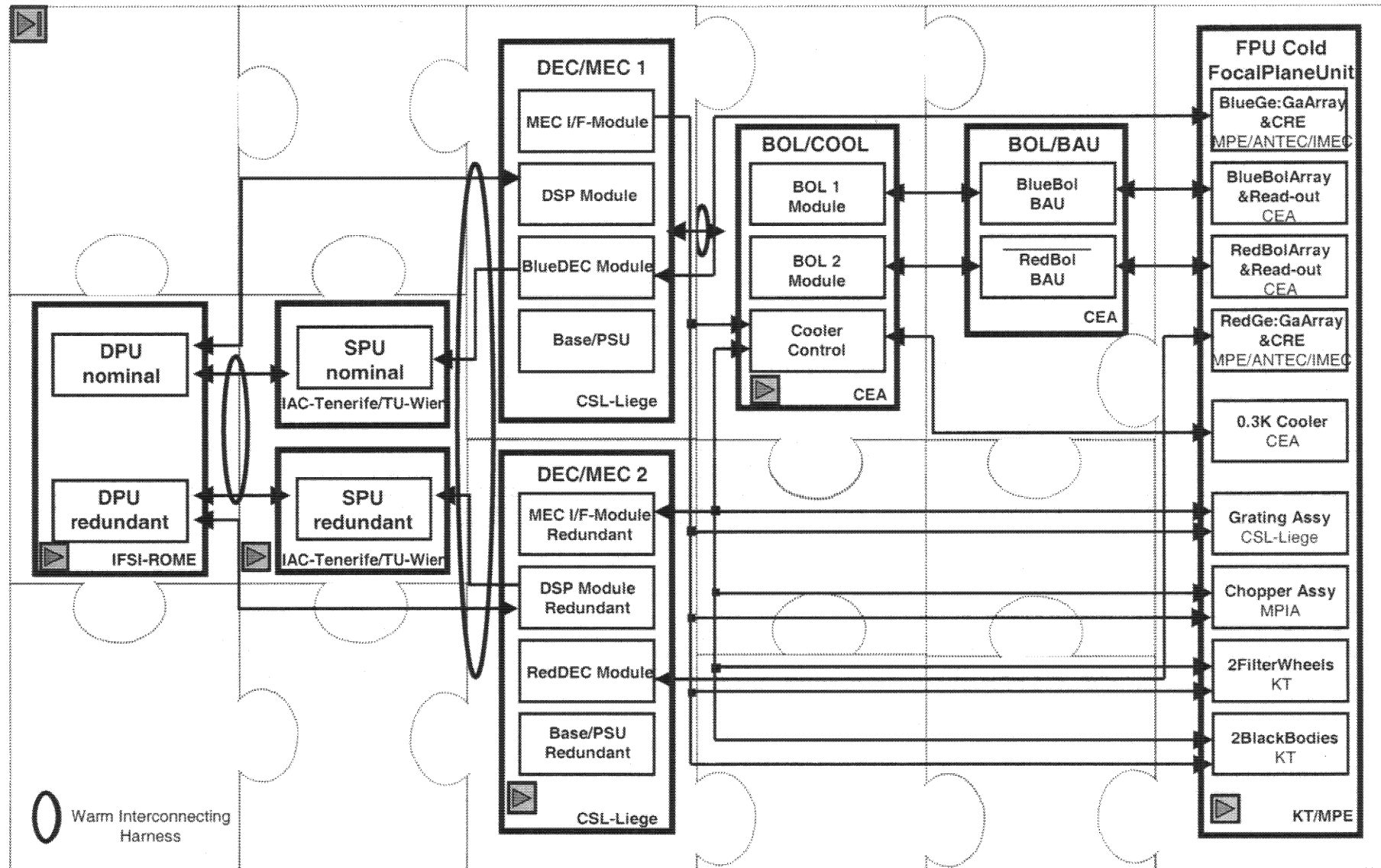




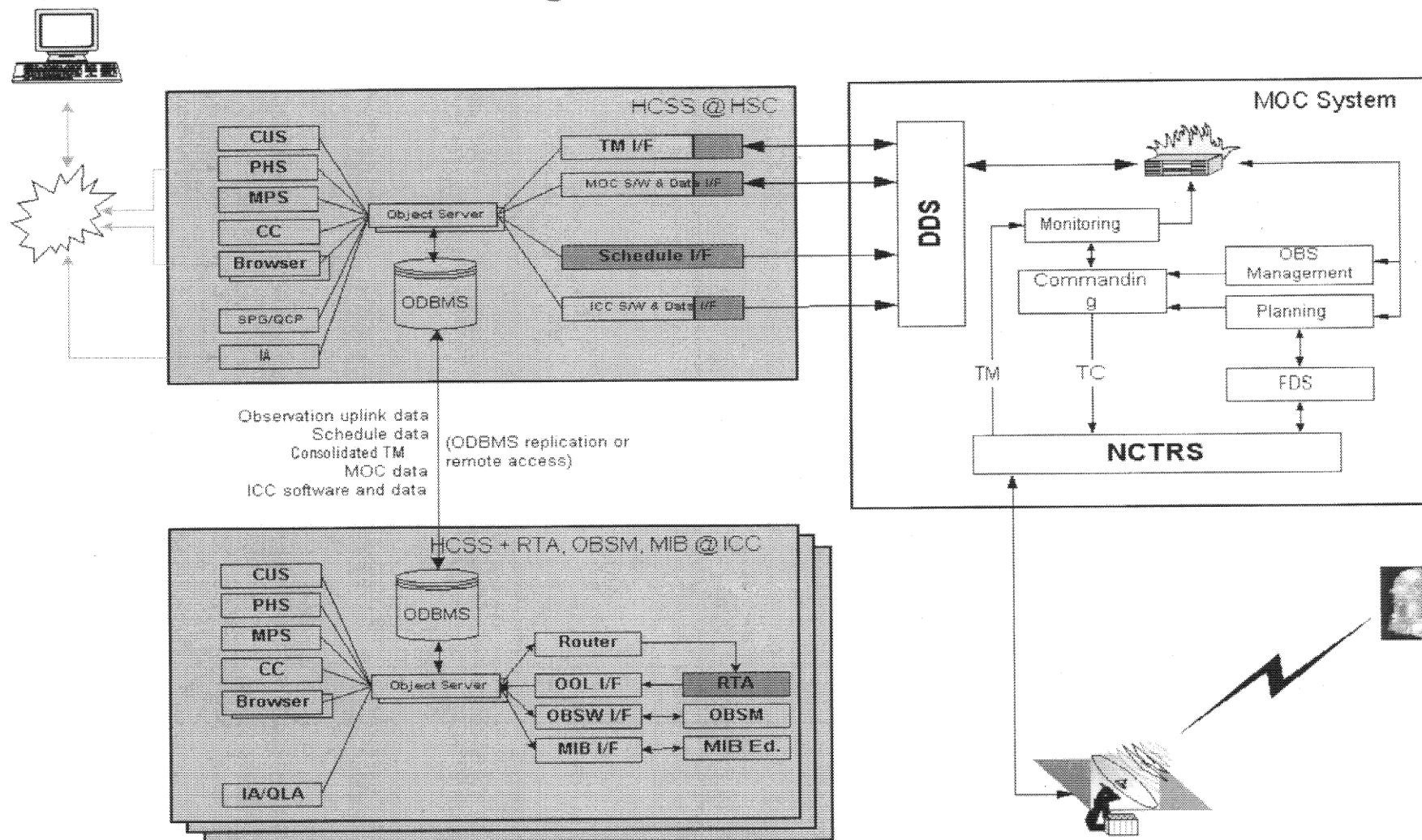
Instrument EGSE for IST and its Interfaces to CCS

Otto H. Bauer
MPE Garching

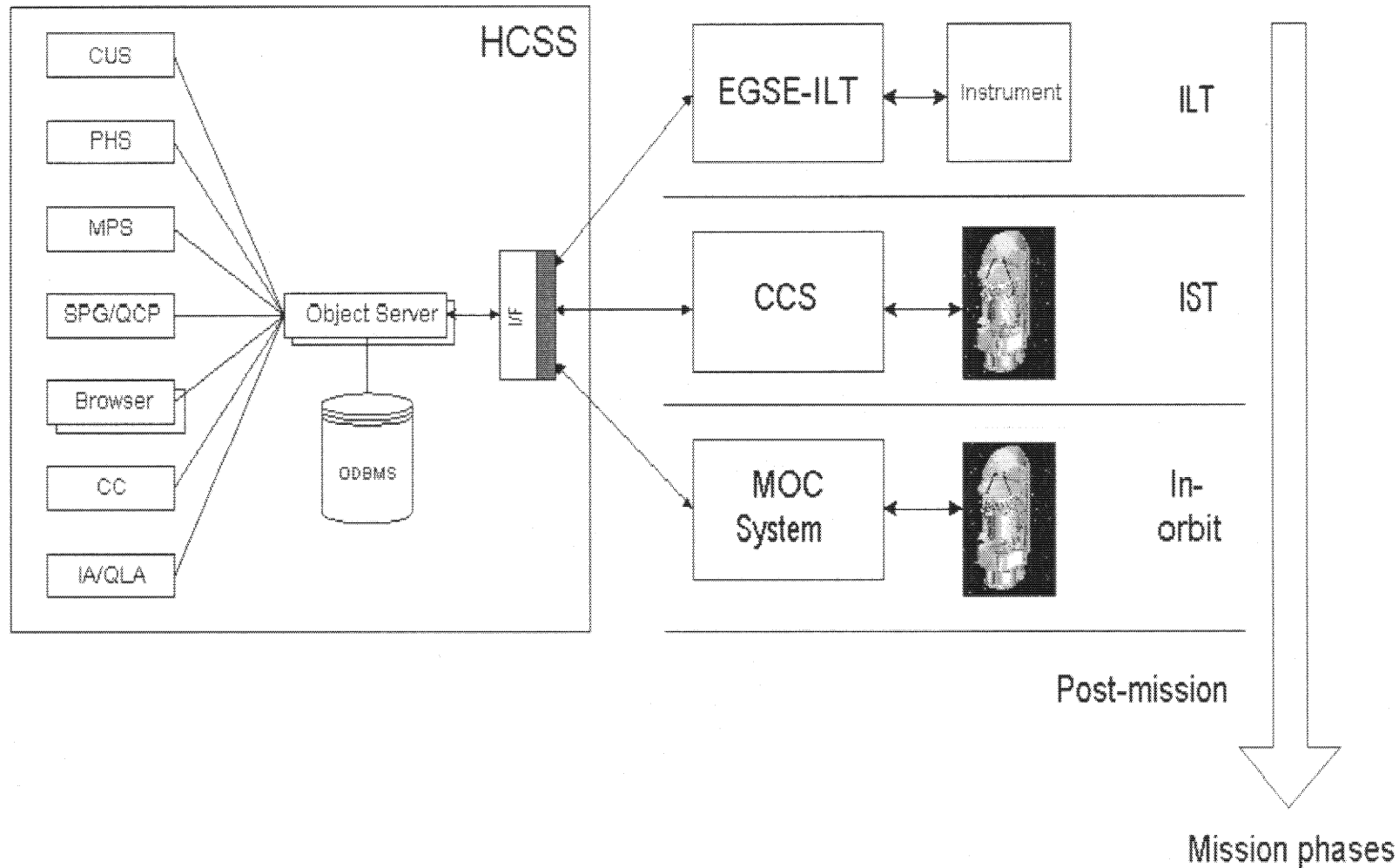
Instrument Overview and Subsystem Responsibilities



Starting Point: Routine Phase

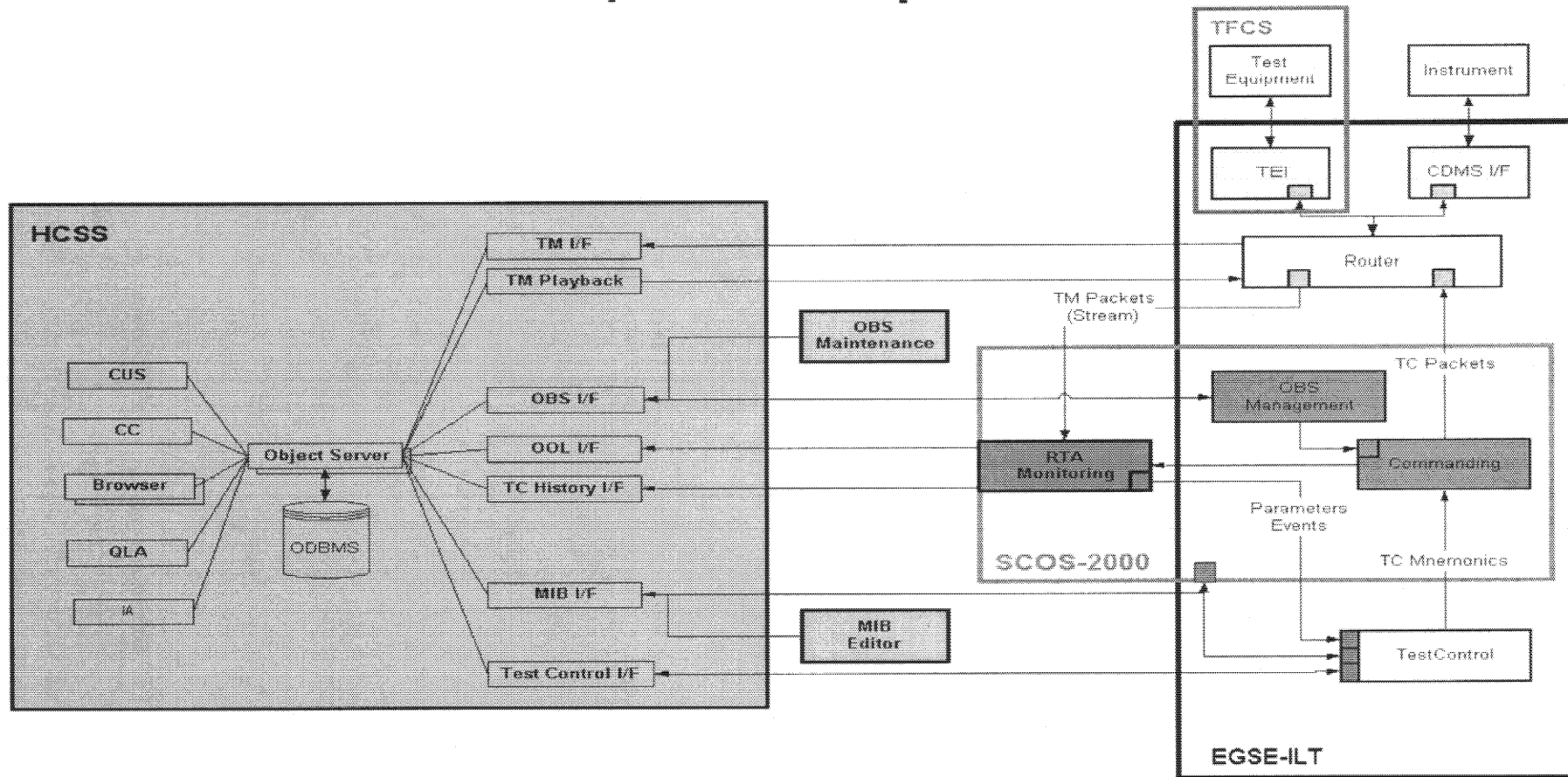


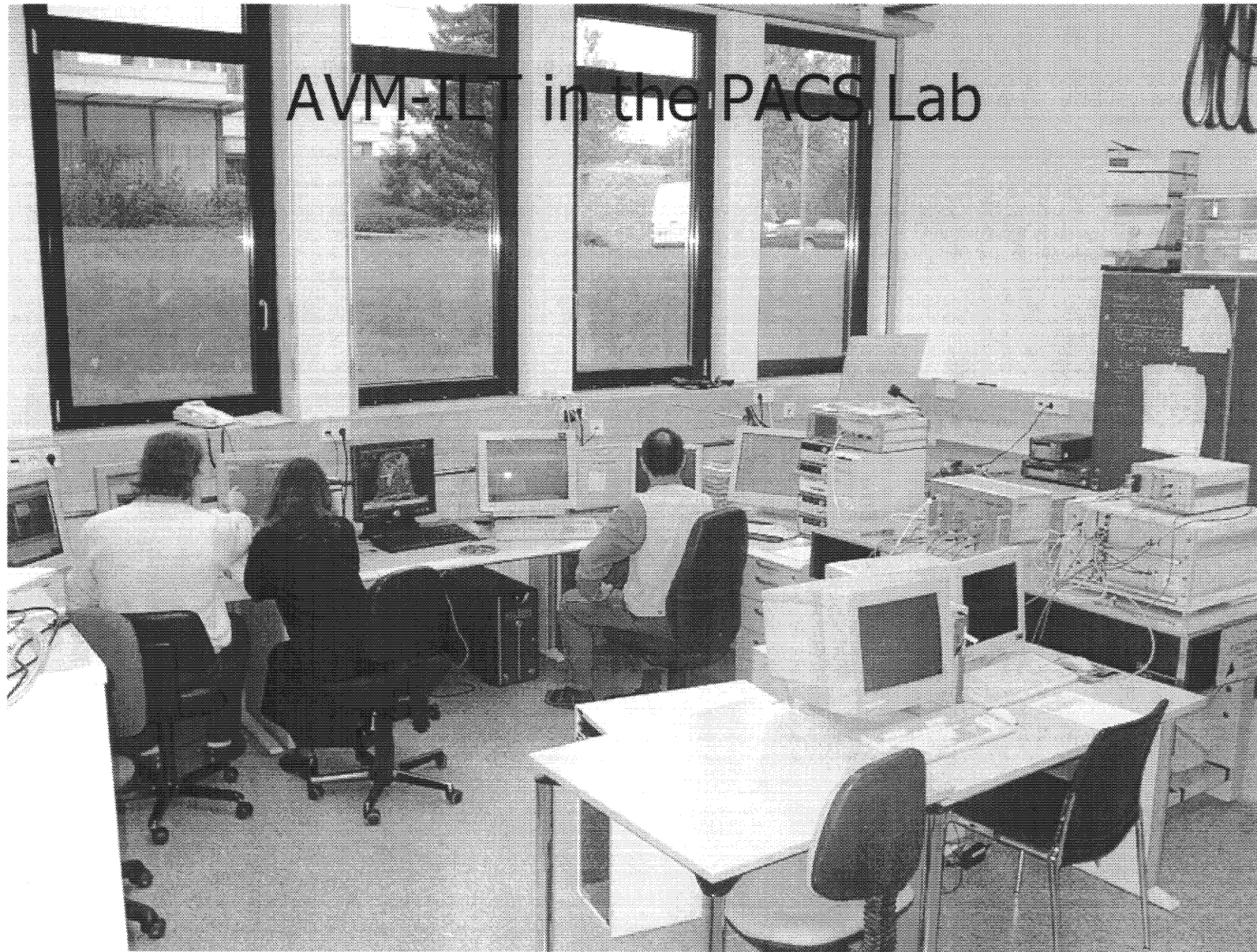
Major Goal: Smooth Transition between Mission Phases



Instrument EGSE for IST

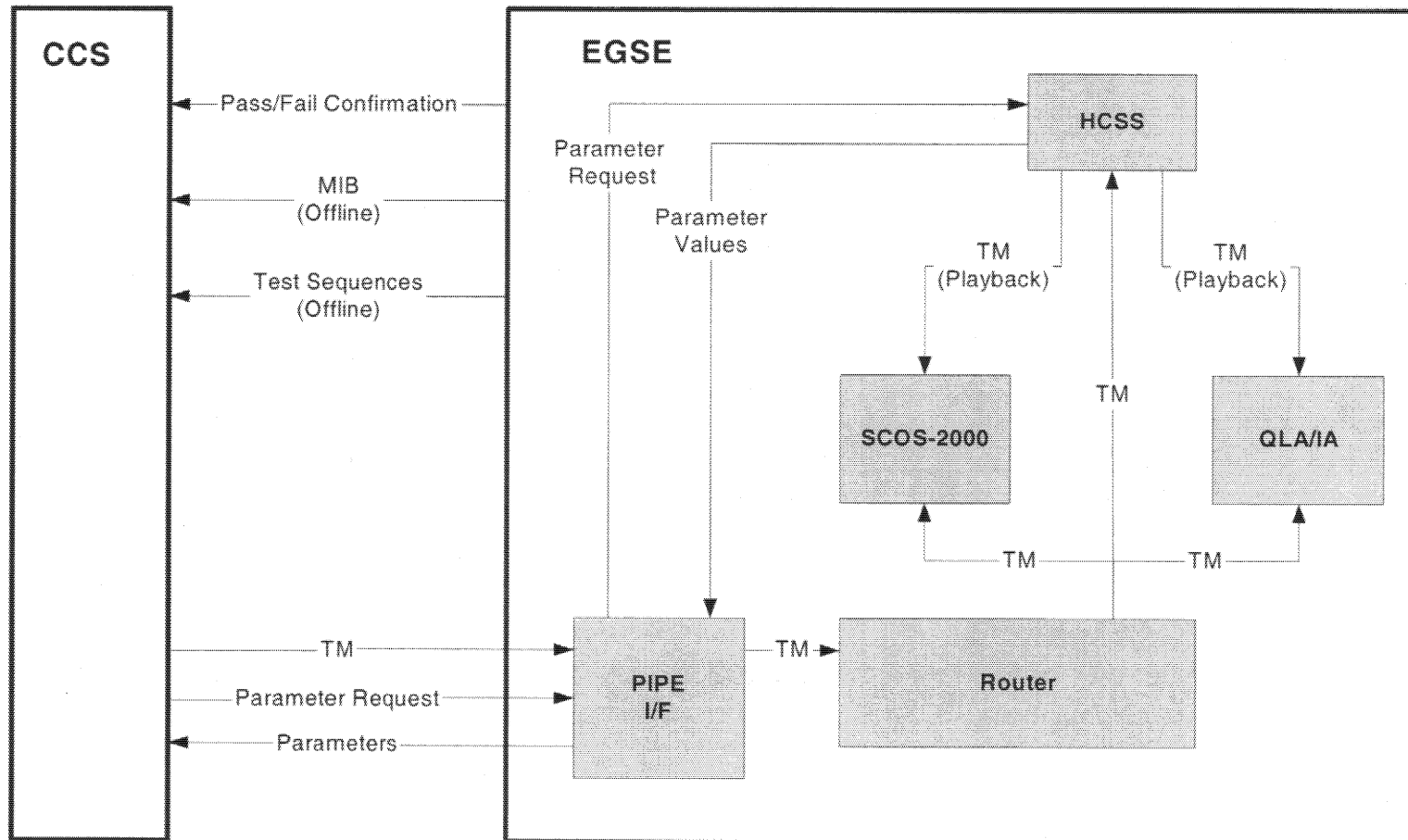
EGSE/HCSS Set-up for ILT





Instrument EGSE for IST

IEGSE for IST



PIPE Interface

- This component interfaces to the CCS using the PIPE protocol (RD02). It handles three types of interaction:
 1. Connection and setup of the interface.
 2. Reception of telemetry packets from the CCS and their transport to the IEGSE Router, which distributes them to the rest of the IEGSE.
 3. Reception of requests from the CCS for the values of parameters to be inserted into the command sequences, which are sent to the instrument. These requests are passed to the HCSS (CUS), which returns the values required and these are passed on to the CCS.

Definition of an Observation (Test Step)

The starting point is that TestControl sends a request for a certain observation (ObsMode, parameters) to CUS (HCSS) and CUS generates a TC sequence with relative timing. It also calculates the whole duration of this observation.

The output could be:

ObsMode (parameters)

TC-1, ObsId-x

TC-2, BbId-y

wait t1

TC-3, p1

wait t2

TC-4, p2, p3, p4

wait p5

TC-5, p6

TC-5, p7

wait t3

TC-6

wait t4

Variables and Execution

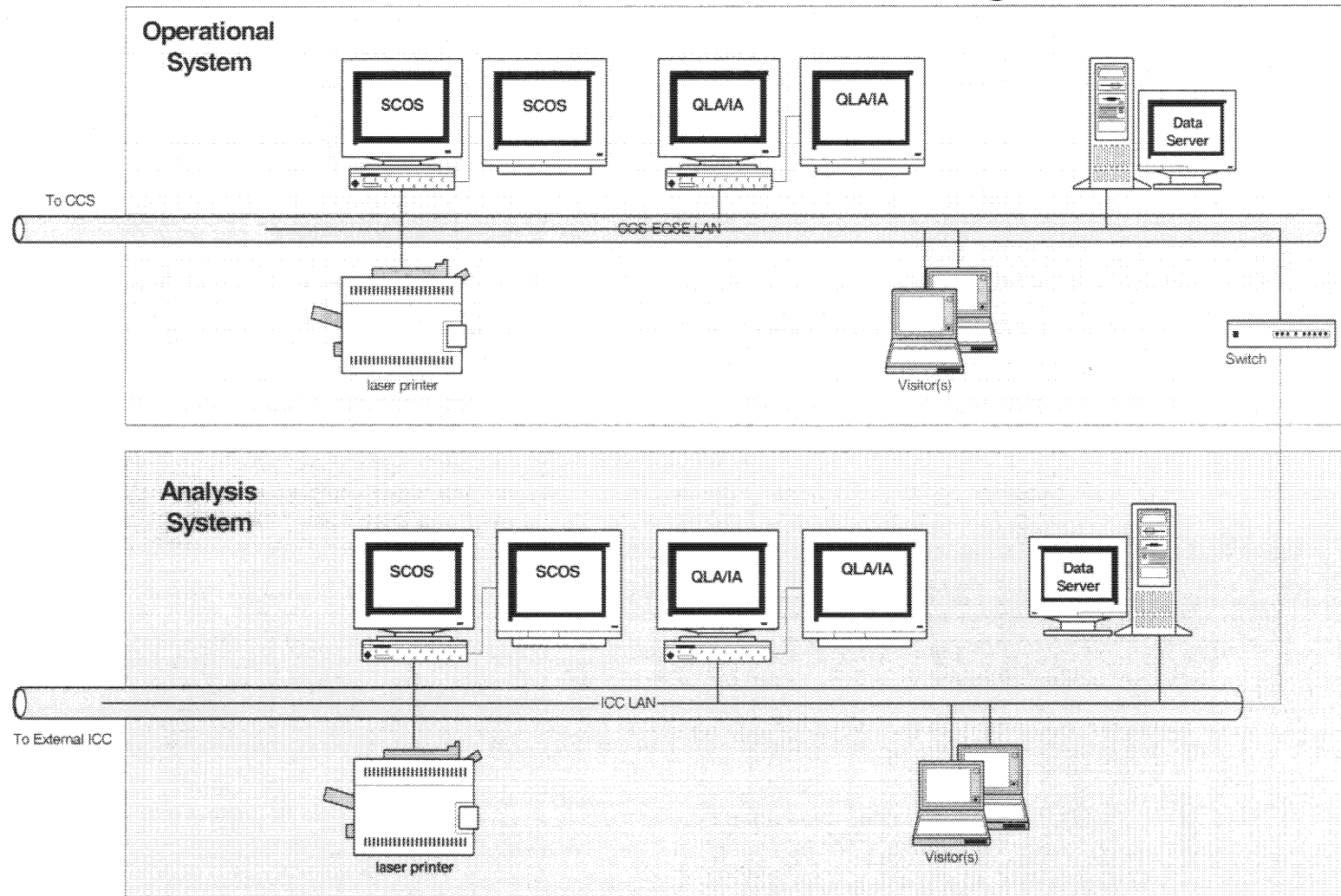
- ObsId-x will change in case of repetition. p_1, \dots, p_7 would be variables which could change of repetition. t_1, \dots, t_4 are fixed waiting times.
- The total duration would be $T = t_1 + t_2 + p_5 + t_3 + t_4$, e.g. T depends on p_5 and this depends on either p_2, p_3 or p_4 .
- It also can be that we have the same TC with different parameters (TC-5 with param. p_6 and p_7) or commands without parameters (TC-6).
- During ILT CUS would delivery back to TestControl the instantiated TC sequence including duration T and
- TestControl would send it via TOPE to SCOS for execution.
- Such an instantiated TC sequence could be given to CCS for execution during short functional tests without instrument participation. In case of repetition of such a sequence ObsID-x could be increment by 1 in a predefined range.
- For the IST, and this could be implemented and tested during ILT, CUS has to be modified in such a way that it generates three outputs:
 - (1) The instantiated TC sequence.
 - (2) The parameterized TC sequence as shown above.
 - (3) The corresponding parameter set
(ObsId-x, $p_1, p_2, p_3, p_4, p_5, p_6, p_7$)
- The parameterized TC sequence could be given to CCS and stored in SCOS. At the time of execution CCS/SCOS sends a request: ObsMode(parameters) to I-EGSE TestControl which starts CUS.
- TestControl will then send the complete parameter set to CSS/SCOS. CCS/SCOS parses the parameters and sends the TC sequence to the instrument.

IEGSE H/W Configuration

- Two complete IEGSE systems will be provided. One is operated in real time during the testing, while the other may be used for analysis of previous test results and acts as a backup for the operational system.

- 6 different items are identified:
 1. SCOS workstation – used primarily to run the SCOS-2000 software. This will be a PC running Linux with a dual display card driving two displays.
 2. Analysis workstation – used to run the instrument analysis software (QLA/IA/PCSS). This will be a PC running Linux with a dual display card driving two displays.
 3. Data Server – used primarily to run the HCSS software. This will be a PC running Linux with a single display and large disk drives with backup facility (to tape/CD TBD)
 4. Colour laser printer
 5. LAN switch - protects the Operational System from the Analysis System allowing access to the external internet from the Analysis System
 6. Laptops – used to run instrument specific analysis tools. These are not provided as part of the EGSE but may be used by instrument experts as necessary during testing.

Herschel Instrument EGSE Hardware Configuration for IST

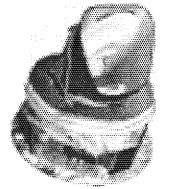
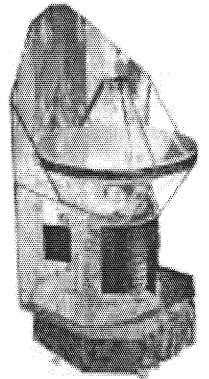


H/W Delivery to Industry

Item	Title	Description
IE-DS-01	Data Server 1	PC running Linux, one Display, keyboard, mouse
IE-DS-02	Data Server 2	PC running Linux, one Display, keyboard, mouse
IE-AN-01	Analysis 1	PC running Linux, two Displays, keyboard, mouse
IE-AN-02	Analysis 2	PC running Linux, two Displays, keyboard, mouse
IE-SC-01	SCOS 1	PC running Linux, two Displays, keyboard, mouse
IE-SC-02	SCOS 2	PC running Linux, two Displays, keyboard, mouse
IE-PR-01	Printer 1	Colour Laser Printer, Type TBD
IE-PR-02	Printer2	Colour Laser Printer, Type TBD
IE-SW-01	Switch	LAN Switch

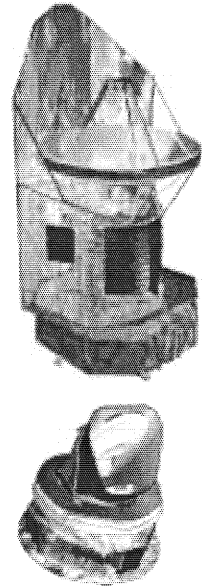
Support from Industry

- Industry will be responsible for providing consumables (printer paper, ink, tapes, CDs) used by the IEGSE
- Industry will be responsible providing a high speed access point to the internet.
- Industry will provide a simulator of the CCS to enable testing of the interface between the CCS and IEGSE. This simulator should:
 - Simulate the connection with the CCS
 - Simulate the protocol necessary to connect to and set up the IEGSE interface
 - Provide telemetry packets corresponding to an instrument executing a command sequence in a test procedure
 - Provide parameter requests corresponding to command sequences in a test procedure
 - Accept parameter values corresponding to the request made to the IEGSE



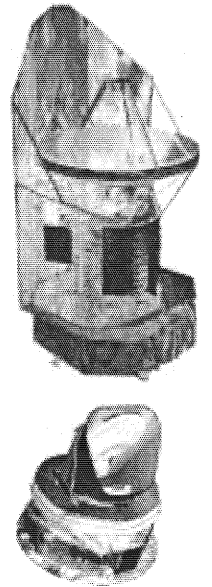
Role of Instrument EGSE at Payload and Satellite level

HP-2-ASED-HN-0265
annex 7



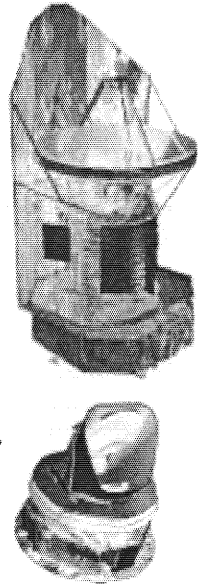
Types of test

- Instruments will be tested with Instrument teams present and absent
- This results in 3 modes of operation for the I-EGSE.
 - Mode 1: I-EGSE OFF (or unavailable)
 - Mode 2: I-EGSE in listening mode i.e. one way communication only from CCS to I-EGSE to dump Instruments HK and Science data
 - Mode 3: I-EGSE involved in real time testing under the control of the CCS
- For mode 1 and mode 2 a predefined set of Observation characteristics can be used (i.e. fixed set of test sequences), executed by CCS.
- For mode 3 the Instrument EGSE needs to be “in the loop”.



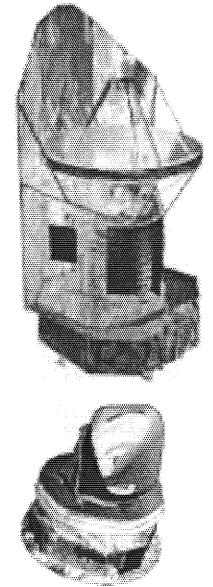
Problem areas

- If stopped for any reason, Instrument command sequences cannot be re-used and require new sets of Observation characteristics before continuing.
- The necessary telecommand data to command an instrument for a specific “observation” is known only to the instrument EGSE and is obtained from the HCSS database.
- Software to determine correct operation of the instrument is resident in the Instrument EGSE.
- Test philosophy demands that the CCS is the only source of telecommands, using a configuration controlled set of test sequences.
- A fixed set of commands with no variability in command data will not support correct operation of the I-EGSE data processing.



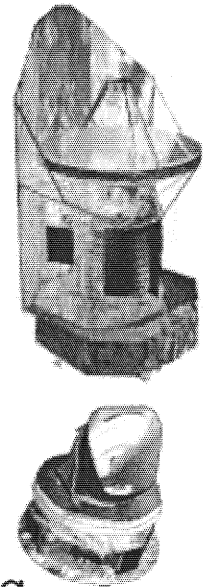
Problem areas

- “Smooth transition” requires that a high level of commonality is required between Instrument level (ILT) and higher levels of test (e.g. IST).
- For ILT the following logic applies:-
 1. start a (TOPE) test sequence
 2. call HCSS to obtain observation telecommand sequence (as another test sequence)
 3. execute the test sequence
 4. perform processing and test pass/fail logic on I-EGSE
 5. confirm pass/fail
 6. continue to next step if pass, else.....
- This method cannot be used on the CCS



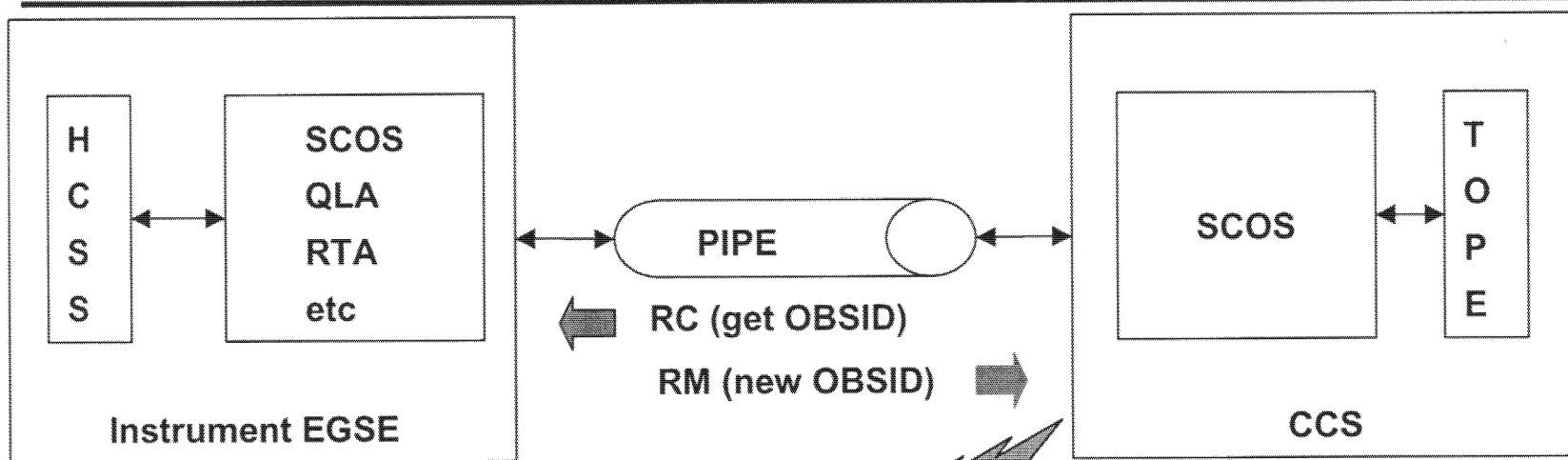
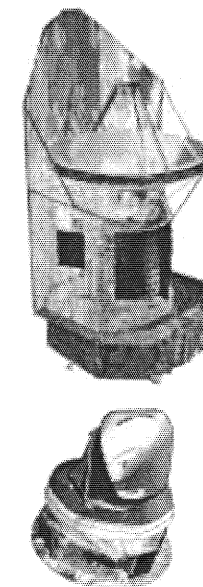
Reasons

- Creating new test sequences dynamically, would bypass the test session management and configuration control mechanism of the CCS.
- The test sequence creation process is performed by the HCSS software inside the I-EGSE which implies:-
 - Either a file transfer of the source of the test sequence from Instrument EGSE to CCS, so that CCS can execute it,
 - Or execution of the sequence by the instrument EGSE resulting in giving it the capability and authority to send telecommands !



Solution

- CCS to request I-EGSE to initiate generation of observation data (using RC command of PIPE protocol).
- Allow I-EGSE to send observation data to CCS for use by CCS test sequences (RM packets of PIPE protocol).
- Use this data to construct “parameters” for a set of generic Instrument operational telecommands.
- CCS then retains commanding responsibility with predefined telecommands, whilst I-EGSE provides dynamic data and all instrument data processing.



1. Set status "ready" & Wait for PIPE messages
2. Receive RC (get obsid)
3. Request new observation from HCSS
4. Construct & send RM (obsid)
5. Wait for new observation data
6. Process and set completion status (by RM)

1. Start test sequence in TOPE and confirm/wait IEGSE status = ready
2. Request new observation data by sending RC command
3. Wait for update of parameter "obsid"
4. On arrival SENDTC with parameter "obsid"
5. Wait for completion status
6. Repeat for more observations.....

Instrument AIT Meeting

PACS Test Program Updates

Reinhard Katterloher
MPE

AVVEX 8

Modifications to the CQM+AVM ILT Program

- ✓ Delivery of CQM FPU to MPE is delayed to 25 August 2003
- ✓ Final delivery date of PACS to ESA is before Christmas 2003

Proposal and Reasoning

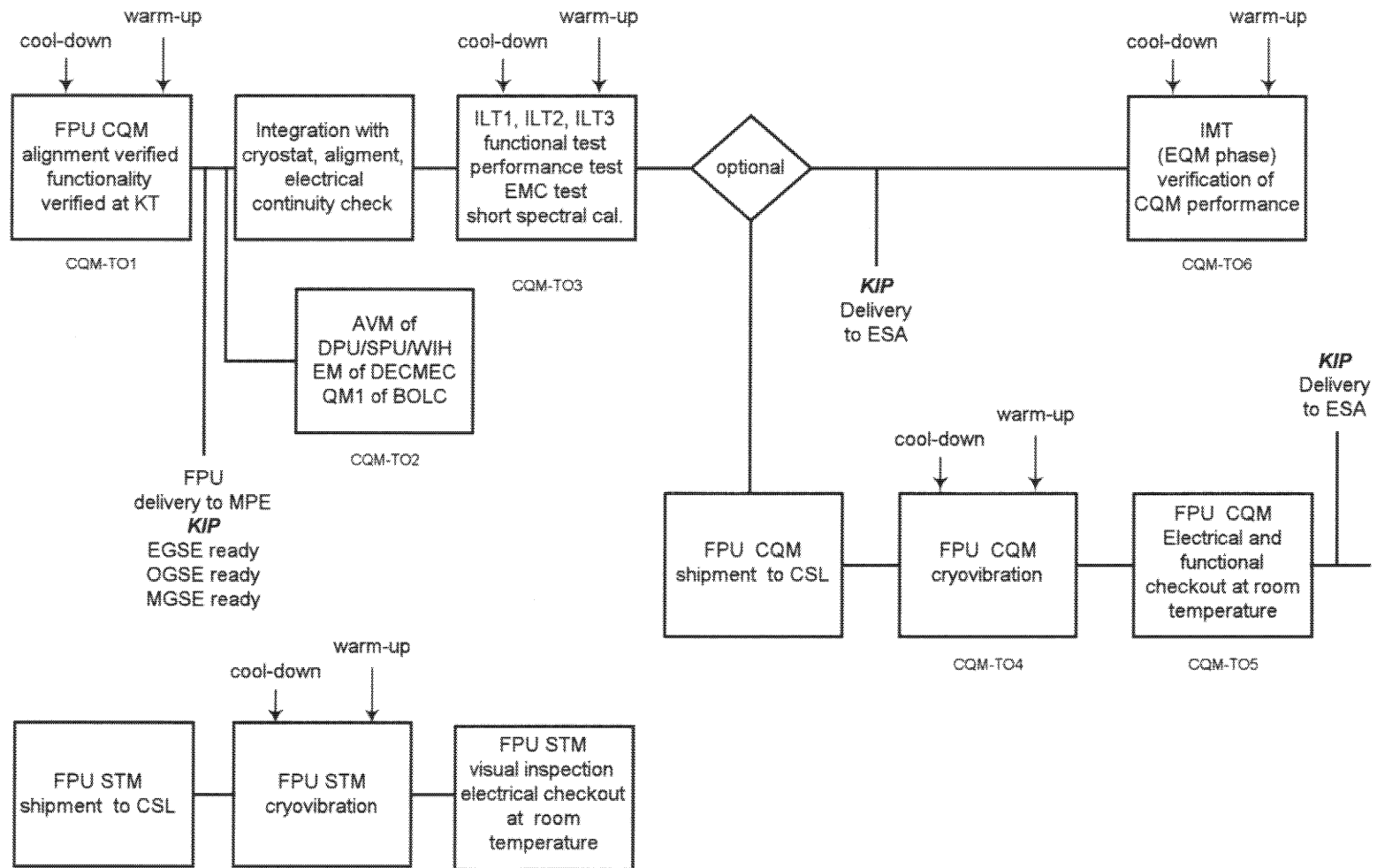
Cryogenic qualification of the FPU will be done with the FPU STM
PACS FPU STM is a rather complete and detailed unit.

Vibration at RT successfully performed and finished yesterday
(minor deviation: lower first resonance in Z but RFW notch depth not exploited.
Final post test review with ESA expert requested)

CQM calibration activities are adapted to a limited but reasonable test time.
ILT phase comprising functional test, performance test and short spectral
calibration can be extended from 1st of September to 19 December 03 (85 days)

In case a cryovibration of the CQM is highly advisable, the verification
of CQM performance needs to be moved to System Level EQM phase.
33 days test slot at CSL could be January 2004, final planning around June 2003

CQM+AVM ILT AIV Sequence



Modified CQM+AVM ILT schedule

ID	Task Name	Start	Finish	Duration	2003		Qtr 3, 2003			Qtr 4, 2003			Qtr 1, 2004			Qtr 2, 2004		
					May	Jun	Jul	Aug	Sep	Oct	Nov	Dec	Jan	Feb	Mar	Apr	May	Jun
1	PACS Master Schedule	09-06-03	15-12-04	398 days														
2	CQM+AVM Phase	09-06-03	15-12-04	398 days														
3	Delivery Ge:Ga Detector arrays to KT	09-06-03	09-06-03	0 days			◆ 09-06											
4	Delivery of BOLC to MPE	28-07-03	28-07-03	0 days				◆ 28-07										
5	Test cryostat + TEI operational, alignment verified	11-07-03	11-07-03	0 days			◆ 11-07											
6	FPU CQM Delivery from KT to MPE	25-08-03	25-08-03	0 days					◆ 25-08									
7	CQM ILT at MPE (sequence TBC)	25-08-03	19-12-03	85 days														
8	ILT1, 1.1-1.4 FPU Integr/cryostat, ei check +cool dow	25-08-03	18-09-03	19 days														
9	ILT1, 1.5 Functional Test + Cooler recycling	19-09-03	23-09-03	3 days														
10	ILT 2 Performance Test Q2.1-Q2.4, Q2.5	24-09-03	29-09-03	4 days														
11	Warm up + venting	30-09-03	08-10-03	7 days														
12	ILT1, 1.1-1.4 FPU/TO re-alignment, cool down	09-10-03	23-10-03	11 days														
13	ILT1, 1.5 Functional Test + Cooler recycling	24-10-03	28-10-03	3 days														
14	ILT 2 Performance Test Q2.1-Q2.4	29-10-03	03-11-03	4 days														
15	ILT EMC tests	04-11-03	10-11-03	5 days														
16	ILT 2 Short spatial / spectral performance Q2.5, Q2.6	11-11-03	18-11-03	6 days														
17	Calibration C3.1-3.5, 3.6 gas cell	19-11-03	24-11-03	4 days														
18	Calibration C3.7, 3.10,	25-11-03	27-11-03	3 days														
19	Margin	28-11-03	04-12-03	5 days														
20	Warm up + venting	05-12-03	15-12-03	7 days														
21	Preparation for shipment to ESA or CSL	16-12-03	19-12-03	4 days														
22	EQM Test Phase at ASPI (tentative)	22-12-03	15-12-04	258 days														
23	CQM cold vibration at CSL (tentative)	22-12-03	06-02-04	35 days														
24	Incoming inspections.Integr. w. cryostat/Tests (TBC)	12-02-04	15-12-04	220 days														
25	Verification of Functionality and Performance (TBC)	05-04-04	16-04-04	10 days														

Unit	Model	Form	Fit	Function	Redundancy	Remark
DPU	AVM	x	x	x	No redundancy foreseen for AVM	PFM fully redundant
	PFM	x	x	x		
SPU	AVM	Delivered as Rack, mountable on SVM TBC	x	x	No redundancy foreseen for AVM	PFM fully redundant
	PFM	x	x	x		
DECMEC	EM	Delivered as Rack, mountable on SVM TBC	x	x	No redundancy foreseen for AVM	PFM partially redundant (MEC1, MEC2)
	PFM	x	x	x		
BOLC	QMI	Delivered as Rack, mountable on SVM TBC. Different mounting pattern.	(x)	Delivered without power supply External power supply needed.	No redundancy foreseen for AVM	PFM partially redundant
	PFM	x	x	x		
All AVM WE units are not black painted						
WIFI	AVM	x	x	x	N.A.	Identical with PFM harness; back-shells to be discussed
	PFM	x	x	x	N.A.	
FPU	CQM	x	x	<ul style="list-style-type: none"> • Full optics • All mechanisms complete • Both Photoconductor arrays working, but only 2x12 modules integrated instead of 2x25 • Both bolometer arrays completely equipped, but only 50% in each array with full IR performance 	Same redundancy of mechanisms and temp sensors as PFM	
	PFM	x	x	x	see CQM	

Status 21 January 2003

Name	Dep./Comp.	Name	Dep./Comp.
Alberti von Mathias Dr.	SM 34	Sachsse Bernt	ED 21
Alo Hakan	OTN/IP 35	Schäffler Johannes	OTN/EN 64
Barlage Bernhard	ED 11	X Schink Dietmar	ED 422
X Bayer Thomas	ED 541	X Schlosser Christian	OTN/EN 64
X Faas Horst	EA 65	Schweickert Gunn	SM 34
Fehringer Alexander	SM 33	Stauss Oliver	SM 33
Frey Albrecht	ED 422	Steininger Eric	ED 422
Gerner Willi	ED 13	X Stritter Rene	ED 11
Grasl Andreas	OTN/EN 64	Suttner Klaus	SM 32
Grasshoff Brigitte	ED 521	Tenhaeff Dieter	SM 34
Hartmann Hans Dr.	ED 422	Thörmer Klaus-Horst Dr.	OTN/ED 65
X Hauser Armin	SM 31	Wagner Adalbert	OTN/IP 35
Hinger Jürgen	SM 31	Wagner Klaus	SM 31
X Hohn Rüdiger	ED 541	X Wietbrock, Walter	ED 521
X Hölzle Edgar	ED 421	Wöhler Hans	SM 34
Huber Johann	ED 543	Zipf Ludwig	ACE 32
Hund Walter	SE 76		
X Idler Siegmund	ED 432		
Ivány von András	ACE 32		
Jahn Gerd Dr.	SM 31	X Alcatel	ASPI
X Kalde Clemens	ED 532	X ESA/ESTEC	ESA
Kameter Rudolf	OTN/EN 64		
X Kersting Stefan	OTN/EN 63	Instruments:	
Kettner Bernhard	SM 34	X MPE (PACS)	MPE
Knoblauch August	ED 531	X RAL (SPIRE)	RAL
X Koelle Markus	ED 533	X SRON (HIFI)	SRON
X Kroeker Jürgen	ED 542		
Kunz Oliver	SM 31	Subcontractors:	
Lamprecht Ernst	OTN/SM 222	Air Liquide	AIR
X Lang Jürgen	SE 76	Alcatel Bell Space	ABSP
Langfermann Michael	ED 541	Astrium Sub-Subsyst. & Equipment	ASSE
Mack Paul	OTN/EN 64	Austrian Aerospace	AAE
X Moritz Konrad Dr.	ED 65	APCO Technologies S. A.	APCO
Müller Lutz	OTN/EN 64	Astrium GmbH Space Infrastr.	ASIP
Muhl Eckhard	OTN/EN 64	BOC Edwards	BOCE
X Pastorino Michel	ASPI Resid.	Dutch Space Solar Arrays	DSSA
Peitzker Helmut	ED 65	EADS CASA ESPACIO	CASA
Peltz Heinz-Willi	SM 33	Eurocopter	ECDE
X Peters, Gerhard	ED 531	HTS AG Zürich	HTSZ
Pietroboni Karin	ED 65	Linde	LIND
Puttlitz Joachim	OTN/EN 64	Patria New Technologies Oy	PANT
X Rebholz Reinhold	ED 541	Phoenix, Volkmarsen	PHOE
Reuß Friedhelm	ED 62	Rembe, Brilon	REMB
X Rühle Wolfgang	ED 6	SENER Ingenieria SA	SEN
Runge Axel	OTN/EN 64	Stöhr, Königsbrunn	STOE